

AKD1500 Neuromorphic Processor PCIe Host Interface Variant System Hardware Data Sheet

Version 1.4

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Revision History:

Version	Note
1.4	Remove SPI interface part numbers and military part numbers.
1.3	Update branding, cover page. Add device nomenclature. Add ordering information.
1.2	Add timing specifications. Add theta Ja Jb, Correct Tj min max. Add parameters for the clock input and xtal. Add layout guidelines. Fix document cross-referencing. Added target application. Add clocking modes.
1.1	Add ball composition and humidity.
1.0	Add specs for VPH33; Add 0.8V current spec. Add block diagrams and supported modes for HRC.

References:

- [1] PCI Express Base Specification, Rev. 2.1, PCI-SIG, 2009
- [2] JEDEC J-STD-020, Moisture/Reflow Sensitivity Classification for Nonhermetic Surface-Mount Devices
- [3] JEDEC JESD22-A114, Electrostatic Discharge (ESD) Sensitivity Testing — Human Body Model (HBM)
- [4] EU Directive 2011/65/EU (RoHS) — Restriction of the Use of Certain Hazardous Substances in Electrical and Electronic Equipment
- [5] BrainChip MetaTF Development Environment — Documentation

Acronyms:

NN	Neural Network, a network of neural processing cores
MM	Mesh Network Packet, containing event data transferred between neural processing cores
SS	Sub-system
NPU	Neural Processing Unit
NPE	Neural Processing Engine
EE	Execution Engine
HPC/HRC	High Performance/Resolution Convolution – Image to Events converter

1.1.1 Features

- 32-Core low-power Neural Processor
- Based on BrainChip's Akida1.0 IP.
- 8-bit x 8-bit x 3-ch front end convolution
- 4/2/1-bit activations on inner layers
- Supports multi-modal models
- Automatic model sequencing (Partial Reconfiguration)
- Edge Learning
- Easy to use, BrainChip's MetaTF development environment
- Interrupt on completion
- Up to 24 GPIO pins

Host drivers available:

- PCIe x2 Gen2
- SPI

- Voltage: 0.8V (core), 1.8V (io), 3.3V (PCIe)

- Also available as IP

- Applications

- Image Classification
- Object Detection
- Regression
- Face Recognition
- Keyword Spotting
- Anomaly Detection
- Point Cloud Classification

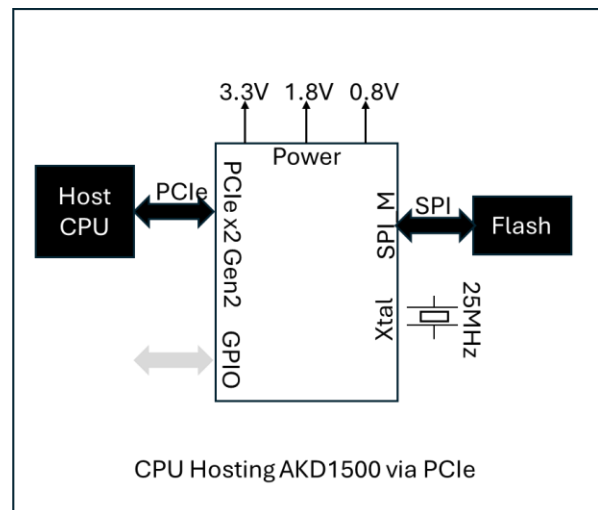
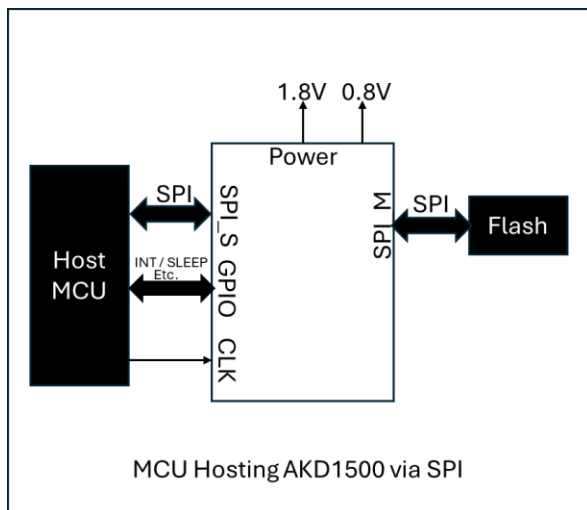


Figure 1: Typical Configuration

2 INTRODUCTION

This document contains the AKD1500 Neuromorphic Processor data sheet and hardware design information, showing how to use the AKD1500 in a system. It is intended for system hardware engineers designing a board that includes the AKD1500 chip and for system software engineers developing products that incorporate the AKD1500.

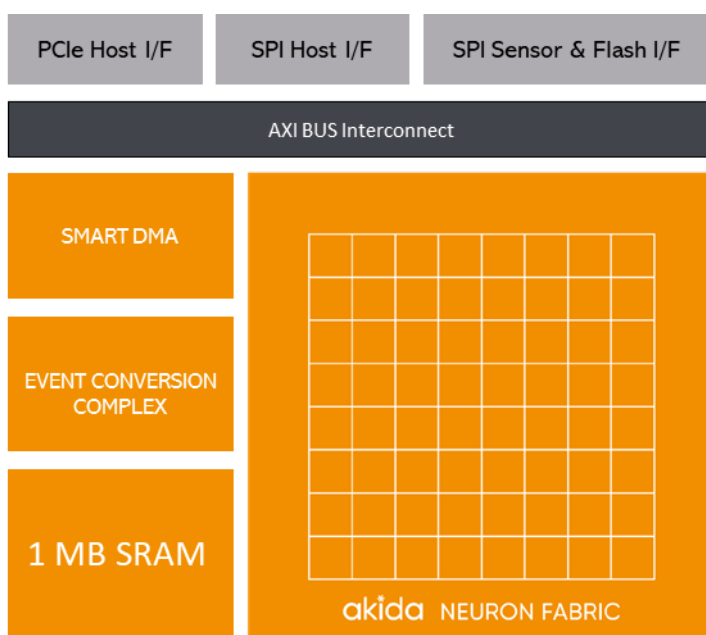


Figure 2: Neural fabric, image to spike converter, and peripheral I/O channels

The AKD1500 Neuromorphic Processor is targeted at the fast, self-contained execution of neural networks. To that end, the chip contains a neural fabric of 32 parallel Neural Processing Units (NPUs), arranged in 8 Physical Nodes that are interconnected through an on-chip mesh network.

Neural networks run entirely within the neural fabric, whereby each individual NPU addresses its own memory, thereby avoiding memory contention.

The integrated PCIe or SPI interfaces are used to initialize the neural fabric with weight values and configuration details that can be stored in external flash memory.

The chip contains a 24-bit data to events converter for generating image events for the AKIDA neural fabric. Details of the internal interconnections of various blocks are shown in the following block diagram:

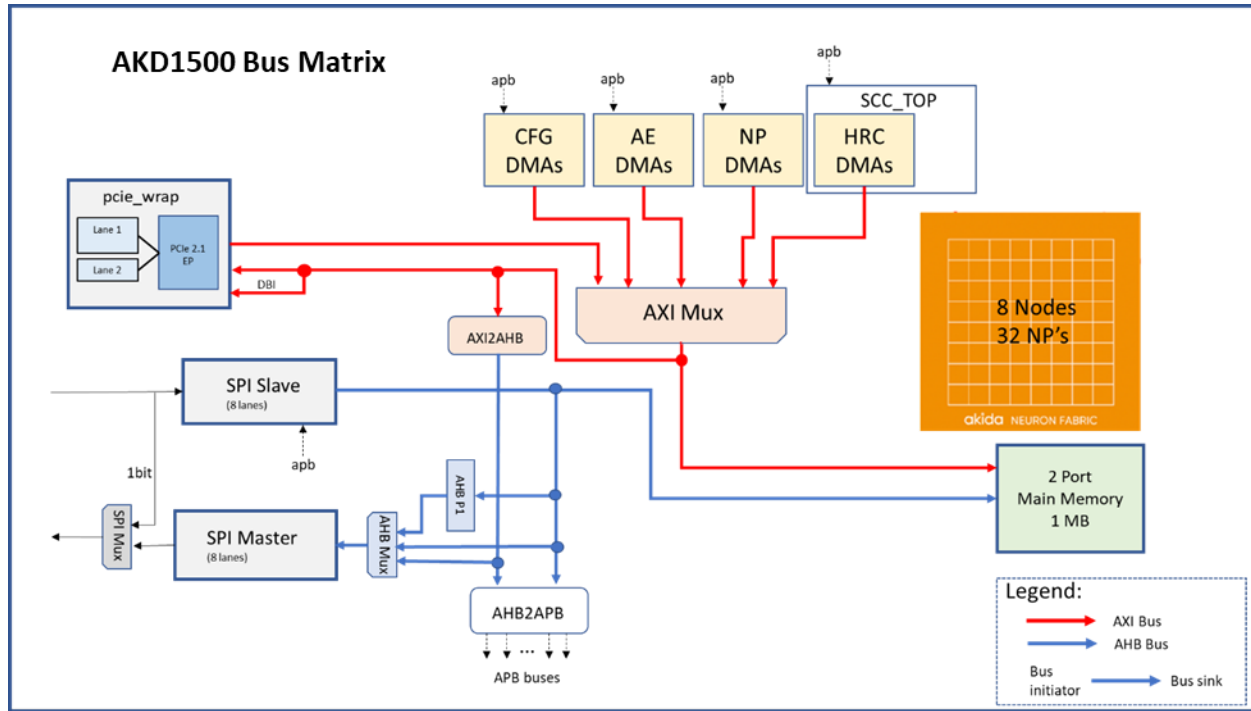


Figure 3: AKD1500 Bus Matrix

2.1 TARGET APPLICATIONS

The Akida AKD1500 from BrainChip is an ultra-low-power, event-based neuromorphic AI processor designed for developing edge AI solutions. It mimics brain-like processing by analyzing only essential sensor data, enabling highly efficient, on-chip learning that reduces power consumption, latency, and reliance on the cloud.

This technology is ideal for industries such as **consumer electronics** (smart homes, wearables), **Industrial IoT** (predictive maintenance, automation), **security** (intelligent surveillance), **AIoT**, and **healthcare** (vital sign monitoring).

Industry	Applications/Use Cases
Consumer Electronics	Smart home devices (e.g., automatic doorbells, appliance voice interfaces), wearables (e.g., fitness trackers, smart glasses, presence detection), personal electronics.

Industrial IoT (IIoT)	Predictive maintenance, industrial automation, robotics (including autonomous quadruped robotics), intelligent sensors, vibration detection, anomaly detection.
Security	Intelligent surveillance systems, biometric recognition, post-quantum cryptographic security, cybersecurity acceleration.
Healthcare	Vital sign monitoring, seizure prediction (in wearables), medical device control, audio enhancement for hearing assistance.
Aerospace & Defense	Low Size, Weight, and Power (SWaP) machine learning applications in spacecraft and robotics, defense and intelligence applications.
Robotics	Autonomous navigation, object detection and classification, gesture recognition, AI for industrial and service robots.
Other	Low power applications

3 AKD1500 BLOCK DESCRIPTIONS

3.1 GENERAL

3.2 CLOCKING MODES

3.2.1 PLL Setup

In Normal Mode (OP_MODE=0), the default setup of the PLL is such that the AKD1500 internal logic is clocked at 400MHz, based on a 25MHz input reference clock. After reset, once the PLL locks, the clocking logic automatically switches from the slow reference clock to the fast PLL's output clock.

3.2.2 Host Select

The input pin PCIE_HOST_SEL determines which host interface is used in the AKD1500. When set to 1, the PCIe Interface is used, when set to 0, the SPI Slave is used. The unused interface will have its clocks turned off automatically.

3.2.3 Sleep Mode

Sleep Mode can be entered by pulling high the AKD1500 Input pin "SLEEP". All internal clocks will be shutdown, except the ones required to keep the PCIe Link alive (if applicable). PLL and clock dividers are kept active for quick recovery. The SPI slave and master could delay the sleep request until no more transactions are pending.

3.2.4 Safe Mode

In Safe Mode (OP_MODE1 = 1), automatic clock shutdown based on PCIE_HOST_SEL is disabled, and both SPI and PCIe interfaces are active. The automatic switching to PLL clock is disabled in this mode, and PLL manual override is enabled. In safe mode, after Reset, the Host needs to monitor PLL lock and switch the system from reference clock to the fast PLL clock once lock is detected.

3.3 GPIO

- 4-bits of general purpose Input/Output ports.

- Up to 20 of the unused SPI master and SPI slave interface signals can be programmed as GPIO ports.
- Maximum of 24 GPIO pins are available if unused SPI interfaces are utilized for GPIO's.

3.4 SRAM

AKD1500 has 1MB of dual-port memory for expediting data transfers.

3.5 SPI_M (SPI MASTER) INTERFACE ACCESS

AKD1500 SPI_M provides two ways to access SPI: eXecute In Place (XIP) access and TRX FIFO access. XIP access is the preferred method because it requires much less programming effort while converting the 32-bit data access straight into SPI traffic. TRX FIFO access method is only used when single-byte SPI commands need to be issued to the external SPI memory device. SPI_M supports DDR (Double Data Rate) SPI accesses. Table 1 shows the supported SPI protocols.

Table 1: SPI protocols supported by SPI_M

SPI Protocol	XIP support	TRX FIFO support
Single	No	Yes
Dual	Yes	Yes
Dual DDR	Yes	Yes
Quad	Yes	Yes
Quad DDR	Yes	Yes
Octal	Yes	Yes
Octal DDR	Yes	Yes
Hyperbus	Yes	Yes

3.5.1 XIP Access

In order to enable XIP access, the user needs to configure the following registers in SPI_M. The required register values are documented in the subsections that follow. During mission mode, the SPI master is automatically placed in XIP mode.

3.5.1.1 *Baud Rate Select Register*

Offset: 0x14

Unmentioned register bits shall be set to 0.

[15:1] – SCKDV: SSI Clock Divider. The LSB for this field is always set to 0 and is unaffected by a write operation, which ensures an even value is held in this register. If the value is 0, the serial output clock (sclk_out) is disabled. The frequency of the sclk_out is derived from the following equation:

$$F_{\text{sclk_out}} = F_{\text{ssi_clk}} / \text{BAUDR}$$

where BAUDR is any even value between 2 and 65534 ($\text{BAUDR} = \{\text{SCKDV} * 2\}$). For example: for $F_{\text{ssi_clk}} = 3.6864\text{MHz}$ and $\text{BAUDR} = 2$ $F_{\text{sclk_out}} = 3.6864 / 2 = 1.8432\text{MHz}$

3.5.1.2 *Control Register 0*

Offset: 0x00

Unmentioned register bits shall be set to 0.

[31] – SSI_IS_MST: shall always be 1.

[24] – SPI_HYPERBUS_EN: set to 1 to activate Hyperbus mode.

[23:22] – SPI_FRF: select SPI rate: 2'b00 = single; 2'b01 = double; 2'b10 = quad; 2'b11 = octal

[4:0] – DFS: data frame size. Set to 5'h1f for 32-bit serial data transfer.

3.5.1.3 *Slave Enable Register*

Offset: 0x10

Unmentioned register bits shall be set to 0.

[1:0] – SER: Each bit in this register corresponds to a slave select line (SPI_S_2MCS0_N and SPI_S_2MCS1_N) from SPI_M. When a bit in this register is set (1), the corresponding slave select line from the master is activated when a serial transfer begins.

3.5.1.4 *SPI Control Register*

Offset: 0xf4

Unmentioned register bits shall be set to 0.

[27:26] – XIP_MBL: XIP Mode bit length: 2'b00 = 2 bits; 2'b01 = 4 bits; 2'b10 = 8 bits; 2'b11 = 16 bits. Please configure according to the external SPI memory device's requirements.

[25] – SPI_RXDS_SIG_EN: set to 1 to support *rxds* signaling by Hyperbus slave devices during Command-Address (CA) phase.

[20] – XIP_INST_EN: set to 1 to enable the SPI instruction field for XIP transfer.

[18] – SPI_RXDS_EN: set to 1 when using the data strobe input pin SPI_M_DQS to capture read data in DTR mode.

[17] – INST_DDR_EN: set to 1 when the SPI instruction field is in DDR mode.

[16] – SPI_DDR_EN: set to 1 when the SPI is in DDR mode (not the instruction).

[15:11] – WAIT_CYCLES: the wait time between control frames transmit and data reception in SPI clock cycles.

[9:8] – INST_L: SPI instruction length in bits. Set to 2 for 8-bit length.

[7] – XIP_MD_BIT_EN: set to 1 to enable Mode bits in XIP mode, which are always 8 bits and sent after the address field.

[5:2] – ADDR_L: defines the length of the address to be transmitted. The length is ADDR_L x 4 bits.

[1:0] – TRANS_TYPE: address and instruction transfer format. Set to 2 to have both specified by SPI_FRF.

3.5.1.5 *Transmit Drive Edge Register*

Offset: 0xf8

This register is used to control the driving edge of TXD register in DDR mode. Unmentioned register bits shall be set to 0.

[7:0] – TDE: TXD Drive edge register which decided the driving edge of transmit data. The maximum value of this register is = (BAUDR/2) -1.

3.5.1.6 *XIP Mode Bits Register*

Offset: 0xfc

Unmentioned register bits shall be set to 0.

[7:0] – XIP_MD_BITS: XIP mode bits to be sent after address phase of XIP transfer.

3.5.1.7 *XIP INCR Transfer Opcode Register*

Offset: 0x100

Unmentioned register bits shall be set to 0.

[15:0] – INCR_INST: XIP INCR transfer opcode, the instruction field content sent by SPI_M.

3.5.1.8 *SSI Enable Register*

Offset: 0x8

Unmentioned register bits shall be set to 0.

[0] – SSIC_EN: SSI Enable. Enables and disables all SPI controller operations. When disabled, all serial transfers are halted immediately. Transmit and receive FIFO buffers are cleared when the device is disabled. Some SPI controller registers cannot be programmed while the controller is enabled, so the user needs to clear this bit before programming the registers aforementioned.

3.5.1.9 *Example: Micron MT25QL128ABA Serial NOR Flash Memory*

The example below shows the configuration settings for SPI_M to access the Micron flash in quad DDR SPI mode.

```
w fcf20014 00000002 // SPI master AHB; BAUDR
w fcf20000 8080001f // SPI master AHB; CTRLR0
w fcf20010 00000001 // SPI master AHB; SER
w fcf200f4 0811421a // SPI master AHB; SPI_CTRLR0
w fcf200f8 00000001 // SPI master AHB; DDR_DRIVE_EDGE
w fcf200fc 000000cc // SPI master AHB; XIP_MODE_BITS
w fcf20100 0000006d // SPI master AHB; XIP_INCR_INST; 0x6D =
DDR Quad I/O Read
w fcf20008 00000001 // SPI master AHB; SSIENR
```

Figure 4: Micron flash SPI_M configuration example

3.5.1.10 *Example: Winbond W959D8NFYA HyperRAM*

The Hyperbus feature (the protocol based on 8-bit DDR SPI) of SPI_M needs to be enabled in order to access HyperRAM. The example below shows the configuration settings for SPI_M to access the Winbond HyperRAM in Hyperbus mode.

```
w fcf20014 00000004 // SPI master AHB; BAUDR
w fcf20000 81c0001f // SPI master AHB; CTRLR0
w fcf20010 00000001 // SPI master AHB; SER
w fcf200f4 02153832 // SPI master AHB; SPI_CTRLR0
w fcf200f8 00000001 // SPI master AHB; DDR_DRIVE_EDGE
w fcf20008 00000001 // SPI master AHB; SSIENR
```

Figure 5: Winbond HyperRAM SPI_M configuration example

3.5.2 TRX FIFO Access

Because of its low efficiency, the user should only use TRX FIFO access when issuing single-byte command packet on SPI_M. The user needs to program the registers in Section 3.5.1 accordingly before programming DR0 at offset 0x60, the register accessing the top of TRX FIFO. By programming DR0, SPI_M will transmit the data in DR0 on the SPI bus. The example below shows the programming sequence of sending a command byte 0x06 on the SPI bus.

```
w fcf20014 00000002 // SPI master AHB; BAUDR
w fcf20000 80800407 // SPI master AHB; CTRLR0
w fcf200f4 00000202 // SPI master AHB; SPI_CTRLR0
w fcf20010 00000001 // SPI master AHB; SER
w fcf20008 00000001 // SPI master AHB; SSIENR
w fcf20060 00000006 // SPI master AHB; DR0
```

Figure 6: Single byte transmission command on the SPI bus configuration example

3.6 PCIe HOST INTERFACE

The Akida chip can be configured to operate with a PCIe Root Complex or an SPI Master Host. The host port is chosen with the PCIE_HOST_SEL pin.

Table 2: PCIe ID

	Decimal	Hexadecimal
BrainChip PCIe Vendor ID	7804	1E7C
Device ID	42240	A500
Class Code	11	0B

3.6.1 PCIe Endpoint Interface features

- Compliant with PCI Express Gen2 Base specification
- Supports 5.0 GT/s and 2.5GT/s serial data transmission rate per Lane
- Dual Lane
- 100MHz reference clock
- Compliant with applicable non-optional features of the PCIe Base Specification
- Single Function
- Embedded DMA with 2 Read Channels, 2 Write Channels, and support for Linked List mode of operation.
- AKD1500 Endpoint can be PCIe master and initiate transaction to the Root complex
- MSI with Per-Vector-Masking
- 1KB Max Payload Size
- Three BAR of type Mem 64b, with 4MB Size, map the internal local address space into the external PCIe memory space.
- Internal Address Translation Unit provides programmable internal local address offset, with support for BAR matched or address matched translations.
- Automatic Lane Reversal
- Support for all Link Power Management States
- Akida compatible driver available on [GitHub](https://github.com/brainchip/akida-driver).

For more information on the PCIe endpoint controller, refer to the PCI Express Base Specification, Rev. 2.1 (PCI-SIG).

https://www.synopsys.com/dw/ipdir.php?ds=dwc_pci_express_controllers

3.6.2 Driver notes

Note that the supported Linux kernel versions are from 5.4 through 6.8. The driver versions will be updated regularly and new drivers will be available on the BrainChip developer website. 6.8 is current Ubuntu 24.04.1 LTS kernel version, later releases will require a driver update.

3.6.3 When PCIe is not used

When PCIe is not used, it is not necessary to supply power to the PCIe PHY. You can save power by using one of these methods.

- Method 1 (recommended): Tie VP08, VPH33, VPTX008, VPTX108 to ground.
- Method 2: Float VP08, VPH33, VPTX008, VPTX108.

3.7 SPI_S (SPI SLAVE) HOST INTERFACE

The AKD1500 SPI_S interface requires no configuration register programming before operating: the user can access AKD1500 SPI_S interface right away after the chip is out of the reset state. But there are some aspects of the SPI protocol that the user needs to be aware of and pay attention to.

3.7.1 External SPI Host Serial Clock Frequency

The SPI host serial clock frequency must be **no higher** than $\frac{1}{4}$ of that of the internal SPI_S core clock. Thus, the user needs to adjust the serial clock frequency accordingly: after AKD1500 is powered up, the user needs to use slow serial clock since the SPI_S core clock is using the bypassed PLL clock output. After the PLL is enabled and drives the SPI_S core clock, the user can speed up the serial clock. Please refer to application notes for AKD1500 clock programming details.

3.7.2 SPI_S Bus Width Selection

AKD1500 SPI_S supports single (standard), dual, quad and octal SPI frame rates. It does NOT support Double Data Rate (DTR). The AKD1500 input pins SPI_S_MODE0 and SPI_S_MODE1 decide the SPI_S frame rate as shown in Table 3: SPI_S.

Table 3: SPI_S Bus Width

SPI_S_MODE1	SPI_S_MODE0	SPI_S Bus Width
0	0	Single (1 bit)
0	1	Dual (2 bits)
1	0	Quad (4 bits)
1	1	Octal (8 bits)

3.7.3 SPI_S Packet Structure

3.7.3.1 SPI_S Instruction Phase

Every SPI_S frame starts with an 8-bit instruction field. The instruction field selects the access type (Read, Write, Read Request, Read Status, Read1n, Write Status — see §3.7.4). The AKD1500 SPI_S interface supports burst lengths of 1, 4, 8, 16 and 32 four-byte words; 64-word bursts are not supported.

3.7.3.2 SPI_S Address Phase

Following the instruction field comes the 24-bit address field with MSB comes in first. In order to address the internal 32-bit space in AKD1500, the 24-bit SPI_S address field is shifted leftward by two bits before being added to an offset of 0xfc000000. Or:

$$\text{AKD1500_ADDR} = 32'hfc000000 + \{\text{SPI_S_ADDR}[23:0], 2'b00\}$$

In other words the 24-bit SPI_S address is the word address.

3.7.3.3 SPI_S Data Phase

SPI_S receives or transmits in frames of 32 bits. The amount of data to be transmitted or received is defined by the Data Length field of the Instruction phase.

3.7.4 SPI_S Access Types

3.7.4.1 SPI_S Write

SPI_S Write packet is used for transmitting data to AKD1500 when the targeted address resides in AKD1500 (non-SPI-Master memory). Figure below shows the example pseudo code of SPI_S Write operation to XH_2PMEM at 0xFC800100.

```
SPI_TX(0x82); // Instruction; write transfer; size = 8 words
SPI_TX(0x20); // Word address[23:16]
SPI_TX(0x00); // Word address[15:08]
SPI_TX(0x40); // Word address[07:00]
SPI_TX(0x10); // Data [31:24] of word 0
SPI_TX(0x37); // Data [23:16] of word 0
SPI_TX(0x24); // Data [15:08] of word 0
SPI_TX(0x9F); // Data [07:00] of word 0
SPI_TX(0x0C); // Data [31:24] of word 1
SPI_TX(0x07); // Data [23:16] of word 1
SPI_TX(0xDF); // Data [15:08] of word 1
SPI_TX(0xC4); // Data [07:00] of word 1
...
SPI_TX(0xFE); // Data [07:00] of word 7
```

Figure 7: SPI_S Write pseudo code

3.7.4.2 SPI_S Write Status

When the external SPI host writes to the AKD1500 SPI-Master memory space, a Write Status polling command is required to check on the status of the SPI_S Write. This is because SPI_S Write cannot be completed right after the command is issued due to the second serial interface at SPI_M. Figure 8: SPI_S Write Status pseudo code shows an example pseudo code of SPI_S Write Status polling operation to SPI_M at 0xFC000200. Note that there is a dummy clock cycle between the Write Status field and the read field. See the SPI_S Write Status pseudo-code figure above for the command sequence and timing.

```

SPI_TX(0x80); // Instruction; write transfer; size = 1 word
SPI_TX(0x00); // Word address[23:16]
SPI_TX(0x00); // Word address[15:08]
SPI_TX(0x80); // Word address[07:00]
SPI_TX(0x10); // Data [31:24] of word 0
SPI_TX(0x37); // Data [23:16] of word 0
SPI_TX(0x24); // Data [15:08] of word 0
SPI_TX(0x9F); // Data [07:00] of word 0

RDATA = 0x00;
While(RDATA != 0x80) {
    SPI_TX(0xC8); // Instruction; write status; 1 wait
cycle
    SPI_DUMMY(1); // 1 wait dummy cycle
    SPI_RX(RDATA); // Keep reading
}

```

Figure 8: SPI_S Write Status pseudo code

3.7.4.3 SPI_S Read

SPI_S Read packet is used for receiving data from AKD1500 when the targeted address resides in AKD1500 (non-SPI-Master memory). The figure below shows the example pseudo code of a 4 word SPI_S Read operation to XH_2PMEM at 0xFC800100. Note that there are 8 wait cycles between the address field and the read data field. While the example shows a read of 4 words, SPI read operations can be 1, 4, 8, 16 or 32 words. See Table 4: SPI Read operation data packet length (words are 16-bits) for the corresponding read instructions. See the pseudo-code figure above and Table 4 for further details of the SPI_S Read command.

```
SPI_TX(0x61); // Instruction; read transfer; 8 wait cycles;
                // size = 4 words
SPI_TX(0x20); // Word address[23:16]
SPI_TX(0x00); // Word address[15:08]
SPI_TX(0x40); // Word address[07:00]
SPI_DUMMY(8); // 8 wait dummy cycles
SPI_RX(RDATA); // Read data [31:24] of word 0
SPI_RX(RDATA); // Read data [23:16] of word 0
SPI_RX(RDATA); // Read data [15:08] of word 0
SPI_RX(RDATA); // Read data [07:00] of word 0
SPI_RX(RDATA); // Read data [31:24] of word 1
SPI_RX(RDATA); // Read data [23:16] of word 1
SPI_RX(RDATA); // Read data [15:08] of word 1
SPI_RX(RDATA); // Read data [07:00] of word 1
...
SPI_RX(RDATA); // Read data [07:00] of word 3
```

Figure 9: SPI_S Read pseudo code

Table 4: SPI Read operation data packet length (words are 16-bits)

SPI Read Command	Data Packet Length
0x60	1 word
0x61	4 words
0x62	8 words
0x63	16 words
0x64	32 words

3.7.4.4 *SPI_S Read Request, Read Status and ReadIn*

When the external SPI host reads from the AKD1500 SPI-Master memory space, a Read Request and Read Status polling commands are required. This is because the read data for SPI_S Read Request cannot be available right after the command is issued due to the second serial interface at SPI_M. Not until SPI_S Read Status command returns 0x80 can the SPI host issues SPI ReadIn command to retrieve the read data. The figure below shows an example pseudo code of SPI_S Read Request and Read Status polling operation to SPI_M at 0xFC000200. Note that there is a dummy clock cycle in both Read Status and ReadIn commands. See the pseudo-code figure above for the full Read Request, Read Status and ReadIn sequence.

```
SPI_TX(0x22); // Instruction; read request; size = 8 word
SPI_TX(0x00); // Word address[23:16]
SPI_TX(0x00); // Word address[15:08]
SPI_TX(0x80); // Word address[07:00]

RDATA = 0x00;
While(RDATA != 0x80) {
    SPI_TX(0x48); // Instruction; read status; 1 wait
cycle
    SPI_DUMMY(1); // 1 wait dummy cycle
    SPI_RX(RDATA); // Keep reading
}

SPI_TX(0x06); // Instruction; readln transfer; 1 wait cycle;
// size = 8 word
SPI_DUMMY(1); // 1 wait dummy cycle
SPI_RX(RDATA); // Read data [31:24] of word 0
SPI_RX(RDATA); // Read data [23:16] of word 0
SPI_RX(RDATA); // Read data [15:08] of word 0
SPI_RX(RDATA); // Read data [07:00] of word 0
SPI_RX(RDATA); // Read data [31:24] of word 1
SPI_RX(RDATA); // Read data [23:16] of word 1
SPI_RX(RDATA); // Read data [15:08] of word 1
SPI_RX(RDATA); // Read data [07:00] of word 1
...
SPI_RX(RDATA); // Read data [07:00] of word 7
```

Figure 10: SPI_S Read Request and Status pseudo code

3.7.4.5 Receive FIFO Burst Threshold Control

By default SPI_S transmits a single 32-bit word internally every time it receives 32 data bits from the SPI bus. This is because the internal AHB bus has more bandwidth than that of SPI bus such that it is not beneficial to have data words accumulated in the SPI_S receive FIFO before transmitting them on the internal bus. Yet for some applications like programming SPI_M flash device by the external SPI_S host, it is preferred to have data words stored in the receive FIFO before transmitting them internally in bursts. SPI_S' **Receive FIFO Burst Threshold Register** at offset 0x14 assigns the threshold of the burst. Up to the value of 31 can be programmed to this register.

3.8 SPI SLAVE-TO-MASTER (S2M) PIN-MUX ACCESS

AKD1500 supports the feature of providing slave-to-master direct SPI access via pin mux so that the external SPI host can access the external SPI memory device. Table 5 shows the pin-mux internal connection when the register field EN_SPI_S2M of AKD1500 configuration register at offset 0x18 bit [16] is set. **Only the single (standard) SPI mode is supported in the pin-mux direct access mode.**

The SPI slave interface can only receive a 24-bit address field. That 24-bit address can be expanded to 32-bits using the **SPI S2M Remap register** (address 0xfce00050) [31:23] to generate a 32-bit address field on SPI master interface. This enables an SPI host to access up to a 32-bit address range of a memory device connected to the SPI master interface. For example, if the external host needs to access the external SPI flash device at address 0x03004000, it needs to program SPI S2M Remap register with 0x03000000 and issue the SPI access command at address 0x004000.

Table 5: slave-to-master pin-mux internal connection

SPI_S	Direction	SPI_M	Direction
SPI_S_2MCS0_N	Input	SPI_M_CS0_N	Output
SPI_S_2MCS1_N	Input	SPI_M_CS1_N	Output
SPI_S_SCK	Input	SPI_M_SCK	Output
SPI_S_IO0	Input	SPI_M_IO0	Output
SPI_S_IO1	Output	SPI_M_IO1	Input

4 AKIDA NEURAL FABRIC

4.1 INTRODUCTION

The Akida Neural Fabric is self-contained and managed by a runtime library that can run on a host processor.

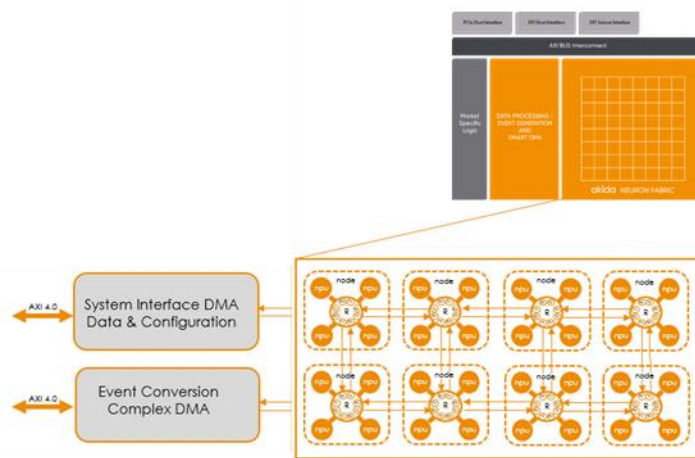


Figure 11: NPU Mesh Network Diagram

Groups of four Neural Processing Units are organized in a node. A mesh network transports spike packets and configuration data between the nodes. An AKD1500 Chip provides a 3 row x 3 column mesh.

4.2 NPU

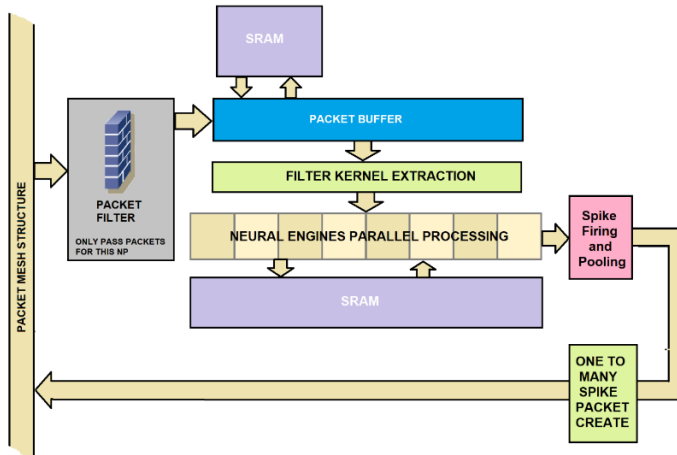


Figure 12: NPU Block Diagram

Each Akida Node has four configurable NPUs with each NPU having eight Parallel Neural Processing Execution engines (NPE) comprising four Execution Engines. NPUs can be configured for Convolutional or Fully connected operation. NPUs have 100KB of SRAM for kernel and neuron potential storage. That SRAM can be reallocated to near NPU's as required.

Other features include:

- Packet based event propagation with configurable packet size
- Multiple networks can co-exist in same device
- Multiple NODEs can be cascaded together on mesh network to create larger Networks.
- On-chip learning in event domain using BrainChip proprietary learning algorithm

4.3 DATA TO EVENTS CONVERTER (HIGH PRECISION CONVOLUTION – HPC)

In addition to the NPU mesh network, there is a High Precision Convolution (HPC) engine. The engine is used primarily to convert 2D arrays of data such as images, and tables into spikes for the NPU mesh network. It can also be configured to do stand-alone convolution separated from the NPU mesh.

The block diagram of the HPC is shown in the figure below. This description will use an image as the 2D input array. There are three channels that each process one of the three input components (RGB). RGB pixels enter the line buffer serially and are output by columns to the variable sized pixel grid. The pixel grid has the same dimensions as the kernel used for the convolution. The operand router connects a pixel and its associated weight to a multiplier in the MAcc. There are

nine 8-bit x 8-bit multipliers per channel. If more than 9 multiplies per channel are required, then the nine multiplier subtotals are accumulated by the Acc block, and it will take multiple clock cycles to calculate the kernel potential. The merge block sums the potentials of each channel to give the total potential.

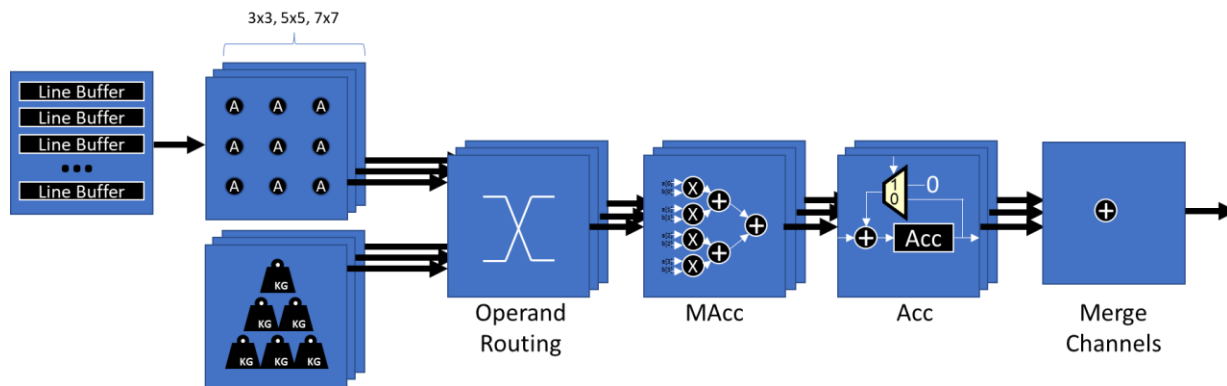


Figure 13: Convolution Math

Line Buffer	Groups input data into lines of 3,5 or 7 lines depending on the kernel size
Vertical Stride	Discards line groups that are not used because of vertical striding
Horizontal Padding	Adds pad value pixels to the left and or right margins based on configuration
Horizontal Stride	Skips horizontally over groups of pixels not used because of horizontal striding
Math	Calculates potential of each filter
Activation	Converts potentials to activations
Horizontal Pooling	Horizontal Stride of 2 or 3 pooling (optional)
Vertical Pooling	Vertical Stride of 2 or 3 pooling (optional)
Pixel to Spike	Converts the sequential stream to an event-based spike

Figure 14: Simplified Pipeline

The HPC engine can be configured with the following parameters.

Parameter	Description
Kernel size	3x3, 5x5, 7x7
Stride	# of pixels or lines to skip between kernel calculations
Padding	Top, bottom, left, right side padding
Pad Data	Data pattern used for pad
Activation	See NPU for activation parameter details

Pooling	Optional 1x2, 2x1, 2x2, 2x3, 1x3, 3x1, 3x2, 3x3

Note: Asymmetrical pooling, above in orange, may not be supported by BrainChip software

Kernel Size	Strides	Supported Padding Configurations (left/top,right/bottom)
3x3	1,2,3	(0,0), (0,1), (1,1), (1,0)
5x5	1,2,3,4,5	(0,0), (1,0), (0,1), (1,2), (2,2), (2,1), (1,0)
7x7	1,2,3,4,5,6,7	(0,0), (1,0), (0,1), (1,2), (2,2), (2,3), (3,3), (3,2), (2,1), (1,0)

Note: The configurations in orange are left priority padding. BrainChip software follows right priority padding. The hardware supports either left or right priority padding.

Input Channels	Kernel Size	Max Filters	Clks per filter	MACC's/Clk
3 (RGB)	3x3	192	1	27
	5x5	64	3	25
	7x7	32	6	24.5
1 (Gray)	3x3	512*	1**	9
	5x5	192	1	25
	7x7	96	2	24.5

* This number is limited to 512 in order to keep the filter variable at 9-bits.

** There are enough multipliers to calculate three 1-channel 3x3 kernels per clock, but the pipeline is limited to processing only one filter per clock.

5 DESIGN DECISIONS

5.1 HOST SELECTION

The AKD1500 can be controlled through a 2-lane Gen2 PCIe or SPI host interface. The choice of host will depend on your cost and performance targets.

In PCIe Mode, the AKD1500 can be a PCIe Master (not to be confused with PCIe Root Complex), and can initiate transactions to access data directly from the Host memory. This allows applications requiring more memory than the available internal SRAM to run.

5.2 EXTERNAL FLASH MEMORY

Storing models in the AKD1500's external flash memory can improve system performance for some applications. The flow chart below, Figure 15: Is flash required? , will help to determine if the external flash is required for your application.

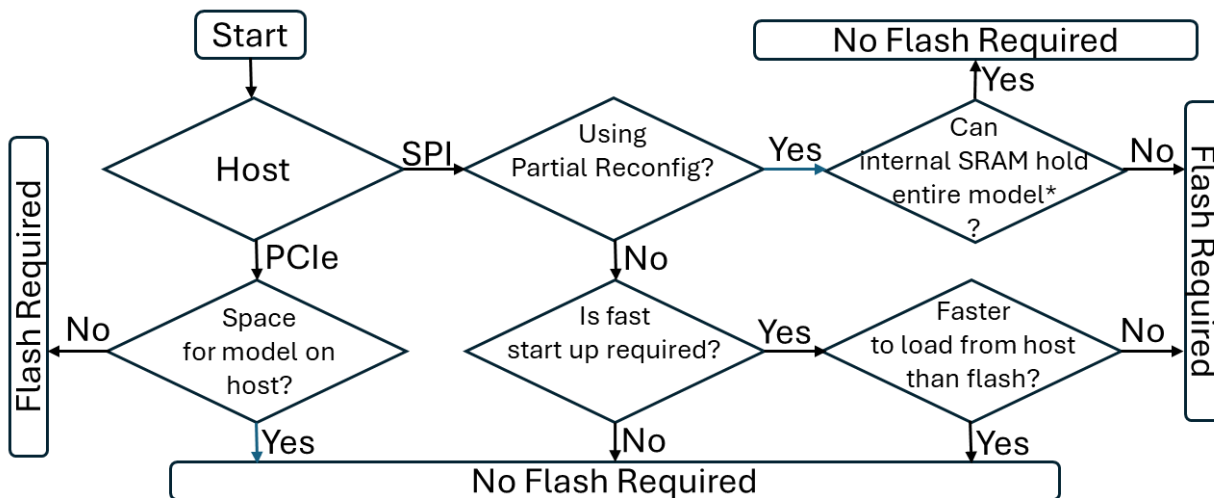


Figure 15: Is flash required?

6 SYSTEM MEMORY MAP

There are two AKD1500 system memory maps, one for PCIe host and Akida core and another for SPI host.

Notes

- Blocks with color are alias that have 2 separate address ranges mapped to the same physical module.
- SPI Slave IP can only access 0xFCxx_xxxx memory space.
- Every bus master has limitation on which bus slave it can access. See "OK Master" column for its permission.
- Accesses to a reserved area will have un-defined behavior and error status response.

Table 6: System Memory Map

Name	Address	Size	OK Master	Note
	0x0000_0000 0x1FFF_FFFF			reserved
XH_2PMEM	0x2000_0000 0x7FFF_FFFF	1 MB	PCIe, Akida	
SPI Master Memory	0x8000_0000 0xBFFF_FFFF	1 GB	PCIe, Akida	External SPI Master flash / memory direct access. Address[31] is inverted before going to SPI Master IP; so it starts with 0.
PCIe Slave	0xC000_0000 0xEFFF_FFFF	1 GB	Akida	To direct access the PCIe host memory.
				reserved
PCIe DBI	0xF8C0_0000 0xF8FF_FFFF	4 MB	PCIe	
				reserved
SPI Master Memory	0xFC00_0000 0xFC7F_FFFF	8 MB	SPI	Use System Conf. Reg. 0x50 to change the upper address[31:23] of SPI Master IP slave AHB bus.

XH_2PMEM	0xFC80_0000 0xFCBF_FFFF	1 MB	PCle, SPI, Akida	Alias of 0x2000_0000 area
Akida APB	0xFCC0_0000 0xFCCF_FFFF	1 MB	PCle, SPI	See Akida Core spec.
				reserved
Sys. Conf. Register	0xFCE0_0000 0xFCE0_0FFF	4 KB	PCle, SPI	Alias of 0xF000_0000
Clock Reset	0xFCE0_1000 0xFCE0_1FFF	4 KB	PCle, SPI	Alias of 0xF000_1000
				reserved
SPI Slave CFG	0xFCF1_0000 0xFCF1_FFFF	64 KB	PCle, SPI	
SPI Master CFG	0xFCF2_0000 0xFCF2_FFFF	64 KB	PCle, SPI	Alias of 0xF3FF_0000
				reserved

7 SYSTEM CONFIGURATION REGISTERS

Acronym:

- RO: Read Only
- RW: Read and Write
- R2C: Read to Clear

The following registers can be accessed through Mesh Network or SPI bus.

Table 7: Chip Info (offset 0x10)

Field	Bits	Type	Reset value	Description
Version	3:0	RO	0x1	The version of the AKD1500 Chip. "1" → the first version.
	7:4	RO	0x0	reserved
OP_MODE	9:8	RO	0x?	This read the status of the chip strap input pin value for operation mode decision.
	11:10	RW	0x0	reserved
PCIE_HOST_SEL	12	RO	0x?	'0' → SPI Host mode. PCIe module is power down. '1' → PCIe Host mode.
SEL_CLK	13	RO	0x?	'0' → Xtal OSC is used as input. '1' → Digital clock is used as input.
	31:14	RO	0x0	Reserved

Table 8: Dual Port Memory Controller (offset 0x14)

Field	Bits	Type	Reset value	Description
LP_DELAY	7:0	RW	0x02	Number of idle clocks before putting SRAM blocks into low power (LP) mode. It is count of 256 clock granularities. "0x01" → 1 x 256 clock delay. "0x02" → 2 x 256 clock delay. ...

LP_REC_TIME	11:8	RW	0x3	Recovery time from LP mode (GF 32Kx32 SRAM needs 6.2ns).
	14:12		0x0	reserved
LP_MODE_EN	15	RW	0x1	'0' = SRAM blocks are never put into low power mode. '1' = allowed SRAM blocks to be put into low power mode.
X_AGING_DELAY	19:16	RW	0x2	Number of continuous transfers before AXI access loses the priority to AHB access.
	23:20	RO	0x0	reserved
H_AGING_DELAY	27:24	RW	0x4	Number of continuous transfers before AHB access loses the priority to AXI access.
	31:28	RO	0x0	reserved

Table 9: Control Signals (offset 0x18)

Field	Bits	Type	Reset value	Description
EN_BUS_RESP	0	RW	0x0	To configure 2P Memory Controller bus interfaces. '0' → Never send error response to AXI or AHB accesses. '1' → Send error response to AXI or AHB accesses if address decoding is out of range with EN_MEM_RANGE = 1.
EN_MEM_RANGE	1	RW	0x0	To configure 2P Memory Controller bus interfaces. '0' → SRAM address range is alias. No address range check. '1' → SRAM address range is checked, and no SRAM write is performed on out-of-range writes.
	3:2	R	0x0	reserved
X_2HBM_NO_WBURST	4	RW	0x0	To enable or disable AHB write burst in AXI to AHB converter of the BM.

				'0' → AXI to AHB converter can use AHB write burst output when AXI has no empty write. '1' → Translate all the AXI write burst to AHB single accesses.
X_2HBM_NO_RBURST	5	RW	0x0	To enable or disable AHB read burst in AXI to AHB converter of the BM. '0' → AXI to AHB converter can use AHB read burst output. '1' → Translate all the AXI read burst to AHB single accesses.
	15:6	R	0x0	Reserved
EN_SPI_S2M	16	RW	0x0	To configure SPI master bus to connect to SPI slave bus directly. '0' → external SPI master bus is connected to SPI Master module (normal operation). '1' → external SPI master bus is connected to SPI slave bus directly; so the host at SPI slave bus can access SPI master bus using 1 bit protocol.
SPIM_DQS_PD	17	RW	0x1	'1' → Enable SPI Master Data Strobe input pulled down. Use it when DQS pin is not used. '0' → Do not enable SPI Master Data Strobe input pulled down.
	19:18			
SPIM_DO_SWAP	20	RW	0x0	'0' → The AHB Write Data bus (h_2spim_hwddata) to SPI Master has NO byte swap. '1' → The AHB Write Data bus (h_2spim_hwddata) to SPI Master has byte swap.

SPIM_DI_SWAP	21	RW	0x1	'0' → The AHB Read Data bus (h_2spim_hrdata) from SPI Master has NO byte swap. '1' → The AHB Read Data bus (h_2spim_hrdata) from SPI Master has byte swap.
	31:22	R	0x0	reserved

Table 10: GPIO Pull Up Enable (offset 0x20)

Field	Bits	Type	Reset value	Description
GPIO_PU	27:0	RW	0x0	'1': enable GPIO[i] pad pull-up resistor. '0': disable GPIO[i] pad pull-up resistor. Note: These signals connect to the IO cell PU directly; no gating.
	31:28	RO	0x0	reserved

Table 11: GPIO Pull Down Enable (offset 0x24)

Field	Bits	Type	Reset value	Description
GPIO_PD	27:0	RW	0x0	'1': enable GPIO[i] pad pull-down resistor. '0': disable GPIO[i] pad pull-down resistor. Note: These signals connect to the IO cell PD directly; no gating.
	31:28	RO	0x0	reserved

Table 12: GPIO Output Data (offset 0x30)

Field	Bits	Type	Reset value	Description
GPIO_IN	27:0	R	0x?	Status of GPIO Pin
	31:28	RO	0x0	reserved

Table 13: GPIO Output Data (offset 0x34)

Field	Bits	Type	Reset value	Description
GPIO OUT	27:0	RW	0x0	GPIO Output value
	31:28	RO	0x0	reserved

Table 14: GPIO Output Data (offset 0x38)

Field	Bits	Type	Reset value	Description
GPIO OE (active high)	27:0	RW	0x0	Output Enable for each GPIO Pin '1': The corresponding GPIO output pin is enabled. '0': The corresponding GPIO output pin is tri stated.
	31:28	RO	0x0	reserved

Table 15: GPIO Mux Enable (offset 0x3C)

Field	Bits	Type	Reset value	Description
GPIO MUX OK	27:0	RW	0x0	To control GPIO to use shared IO. '1': The shared IO pin is selected for the corresponding GPIO signal. '0': The shared IO pin is selected for another signal (not GPIO signal). Note: these signals do not control PU or PD.
	31:28	RO	0x0	reserved

Table 16: GPIO Drive Strength (offset 0x40)

Field	Bits	Type	Reset value	Description
GPIO_DRV	27:0	RW	0x0	Drive strength select for each GPIO pin:

				1'b0: 6 mA 1'b1: 12 mA
	31:2 8	RO	0x0	reserved

Table 17: SPI Slave to SPI Master Memory Remap (offset 0x50)

Field	Bits	Type	Reset value	Description
	22:0			reserved
SPI_S_REMAP	31:23	RO	0x0	This allows SPI Slave IP to access 1 GB external memory in SPI Master bus using 8 MB of window in 0xFC00_0000 to 0xFC7F_FFFF range. The [31:23] bits (8 MB range) become the new haddr[31:23] of SPI Master IP slave AHB address bus.

Table 18: SPI IO Config (offset 0x54)

Field	Bits	Type	Reset value	Description
SPIS_RXEN_ON	0	RW	0x0	'1': Force the IO input buffer is always enabled for SPI Slave IO. '0': Normal mode, IO input buffer is enabled only when is needed for SPI Slave IO.
SPIM_RXEN_ON	1	RW	0x0	'1': Force the IO input buffer is always enabled for SPI Master IO. '0': Normal mode, IO input buffer is enabled only when is needed for SPI Master IO.
SPIM_CLK_ON	2	RW	0x1	'1': Enable SPI Master CLK output. '0': Disable SPI Master CLK output.
SPIM_CLKX_ON	3	RW	0x0	'1': Enable SPI Master CLKX output. '0': Disable SPI Master CLKX output.
SPIS_IO_SLWEN	4	RW	0x1	'1': Enable SPI Slave IO slew rate control. '0': Disable SPI Slave IO slew rate control.
	7:5			reserved
SPIM_IO_SLWEN	8	RW	0x1	'1': Enable SPI Master IO slew rate control. '0': Disable SPI Master IO slew rate control.

SPIM_CS_SLWEN	9	RW	0x1	'1': Enable SPI Master CS slew rate control. '0': Disable SPI Master CS slew rate control.
SPIM_RST_SLWEN	10	RW	0x1	'1': Enable SPI Master RST slew rate control. '0': Disable SPI Master RST slew rate control.
SPIM_DQS_SLWEN	11	RW	0x1	'1': Enable SPI Master DQS slew rate control. '0': Disable SPI Master DQS slew rate control.
	15:12			reserved
SPIS_IO_DRV	17:16	RW	0x3	SPI Slave IO drive strength select: 2'b00: 3 mA 2'b01: 6 mA 2'b10: 9 mA 2'b11: 12 mA
	21:18			reserved
SPIM_DQS_DRV	23:2 2	RW	0x3	SPI Master DQS drive strength select: 2'b00: 3 mA 2'b01: 6 mA 2'b10: 9 mA 2'b11: 12 mA
SPIM_IO_DRV	25:2 4	RW	0x3	SPI Master IO drive strength select: 2'b00: 3 mA 2'b01: 6 mA 2'b10: 9 mA 2'b11: 12 mA
SPIM_CS_DRV	27:26	RW	0x3	SPI Master CS drive strength select: 2'b00: 3 mA 2'b01: 6 mA 2'b10: 9 mA 2'b11: 12 mA
SPIM_RST_DRV	29:2 8	RW	0x3	SPI Master RST drive strength select: 2'b00: 3 mA 2'b01: 6 mA 2'b10: 9 mA 2'b11: 12 mA
SPIM_CLK_DRV	31:30	RW	0x3	SPI Master CLK drive strength select: 2'b00: 3 mA 2'b01: 6 mA 2'b10: 9 mA 2'b11: 12 mA

Table 19: Control Signals (offset 0x60)

Field	Bits	Type	Reset value	Description
EP_APP_LTSSM_EN	0	RW	0x1	'1'= Start PCIe EP Training for PCIE_HOST_SEL=1. Note: When PCIE_HOST_SEL=0 this signal is always 0.
	31:1	R		reserved

Table 20: REG2DBI Control (offset 0x70)

Field	Bits	Type	Reset value	Description
REG2DBI_EN	0	RW	0x0	'1'= Switch PCIe AXI DBI bus to REG2DBI bus. '0'= Normal operation. PCIe AXI DBI bus is connected to the AXI bus matrix.
	3:1	R		reserved
REG2DBI_WDONE	4	R	0x1	'1'= AXI write transfer from REG2DBI done. '0'= AXI write transfer from REG2DBI pending.
REG2DBI_RDONE	5	R	0x1	'1'= AXI write transfer from REG2DBI done. '0'= AXI write transfer from REG2DBI pending.
	31:6	R		reserved

Table 21: REG2DBI Read Data (offset 0x74)

Field	Bits	Type	Reset value	Description
REG2DBI_RDATA	31:0	R	0x0	Last AXI Read Data bits.

Table 22: REG2DBI Write Data (offset 0x78)

Field	Bits	Type	Reset value	Description
-------	------	------	-------------	-------------

REG2DBI_WDATA	31:0	RW	0x0	AXI Write Data bits.
---------------	------	----	-----	----------------------

Table 23: REG2DBI Command and Address (offset 0x7C)

Field	Bits	Type	Reset value	Description
REG2DBI_ADDR	21:0	RW	0x0	AXI AWADDR[21:0] or ARADDR[21:0] address bits.
	23:22	R		reserved
REG2DBI_WSTRB	27:24	RW	0xF	AXI WSTRB
REG2DBI_WREQ	28	W	0x0	'1'=to generate one REG2DBI AXI write transfer. '0'=no AXI write request. Note: a write with this bit = '1' will create 1 clock pulse to start AXI write transfer.
REG2DBI_RREQ	29	W	0x0	'1'=to generate one REG2DBI AXI read transfer. '0'=no AXI read request. Note: a write with this bit = '1' will create 1 clock pulse to start AXI read transfer.
	31:30	R		reserved

8 ELECTRICAL SPECIFICATION

8.1 ABSOLUTE MAXIMUM CONDITIONS

Table 24: Absolute Max Conditions

Symbol	Parameter	Min	Max	Units	Notes
VDD08	Core Power	-0.5	1.000	V	
VP08, VPTX008, VPTX108	PCIe Analog 0.8V	-0.5	1.000	V	
VPH33	PCIe PHY high voltage	-0.5	3.400	V	
DVDD08	PCIe Digital Core Power	-0.5	1.000	V	
AVDD18	PCIe Analog 1.8V	-0.5	2.000	V	

AVD_PLL	Analog PLL Power	-0.5	1.000	V	
VDE18	1.8V Only Power	-0.5	2.000	V	
1.8V PCIe	Dual Voltage Pad 1.8V	-0.5	2.000	V	
3.3V PCIe	Dual Voltage Pad 3.3V	-0.5	3.400	V	
T _{STG}	Storage temperature	-65	150	°C	
T _{LEAD}	Lead temperature during soldering	-	See note 1	°C	
V _{ESD}	Electrostatic discharge voltage (human body model)	-2000	2000	V	2, 3

Notes: 1. Compliant with JEDEC Standard J-STD-020E (for small-body, Sn-Pb or Pb assembly), 2011/65/EU, as amended by 2015/863/EU.
RoHS, and the European directive on Restrictions on Hazardous Substances (RoHS)

2. All specified voltages are with respect to V_{SS}. During infrequent, nonperiodic transitions, the voltage potential between V_{SS} and the V_{CC} may undershoot to -2.0V for periods less than 20ns, or overshoot to V_{CC,max} + 2.0V for periods less than 20ns.

3. JEDEC Standard JS-001

8.2 RECOMMENDED OPERATING CONDITIONS – DEVICE SPECIFIC

8.2.1 DC Electrical Characteristics

All specifications are measured at the package ball

Table 25: Power

Parameter	Symbol	Rating			Units
		Min.	Typ.	Max.	
Core - VDDI Power Supply (Dig)	V _{VDD08}	0.76	0.80	0.84	V
	I _{VDD08}		1.25	2.0	A
LVCMOS 1.8V IO	V _{VDE18}	1.71	1.8	1.89	V
	I _{VDE18}			310	mA
VP08	V _{VP08}	0.76	0.80	0.86	V

Parameter	Symbol	Rating			Units
		Min.	Typ.	Max.	
	V_{VP08_SLEW}			0.1	V/ μ S
	I_{VP08}			76.3	mA
VPTX008, VPTX108	$V_{VPTX008}, V_{VPTX108}$	0.76	0.80	0.86	V
	V_{VPTX08_SLEW}			0.1	V/ μ S
	$I_{VPTX008}, I_{VPTX108}$			33.8	mA
VPH33	V_{VPH33}	3.14	3.3	3.56	V
	V_{VPH33_SLEW}			0.1	V/ μ S
	$I_{VPH33} (x2 \text{ lane})$		30	37.8	mA
	$I_{VPH33} (x1 \text{ lane})$		21	35	mA
Master Clock PLL	$V_{DDAVDPLL}$	0.76	0.80	0.84	V
	$I_{VDDAPLL}$		2.5	5	mA
Junction Temperature	T_j	-40		125	$^{\circ}$ C

8.2.2 IO Characteristics

Parameter	Symbol	Min	Typ	Max	Units	Notes
Input Low Level	V_{IL}	0		0.54	V	
Input High Level	V_{IH}	1.26		1.8	V	
Hysteresis	V_{HYS}	0.18			V	
Output Low Level	V_{OL}	0		0.45	V	
Output High Level	V_{OH}	0.99		1.8	V	
Leakage	I_L			10	μ A	
Pullup/Pulldown	R_{PUD}		50		k Ω	

8.2.3 AC Electrical Characteristics

Table 26: Reference Clocks

Parameter	Symbol	Rating			Units	Notes
		Min.	Typ.	Max.		
External Clock input for software compatibility	$F_{REF \text{ API}}$	25	25	25	MHz	1,2

Parameter	Symbol	Rating			Units	Notes
		Min.	Typ.	Max.		
External Clock input - custom	F _{REF custom}	7		200	MHz	1,2
Reset pulse width	T _{RST(Min)}			1	μS	
Xtal Frequency	F _{XTAL}	20.1	25	30	MHz	1,2
Xtal Internal Shunt Cap.	C ₀		7		pF	4
Xtal Total Load Cap.	C _L		12		pF	4
Xtal Feedback Resistor	R _F		1M		Ω	4
Xtal Equivalent Resistance	ESR		60		Ω	
Xtal Frequency Tolerance	F _{XTAL_TOL}			100	PPM	

Notes:

1. For compatibility with existing software, the xtal or clock input must be 25MHz. With software customization, it is possible to change the F_{REF} to other ranges. If not using the software compatible value, you must bypass the PLL until it has been programmed to the desired custom settings.
2. Crystal and clock input are mutually exclusive. Only one clocking method is allowed.
3. Reset pulse requirement is driven by PLL specifications
4. Refer to Figure 16: Recommended Xtal Configuration. $C_L = C_{PCB_STRAY} + (C_{L1} \times C_{L2}) / (C_{L1} + C_{L2})$. C₀ and ESR are internal properties of the xtal.
5. Xtal values used for qualification: C_{L1} = C_{L2} = 7pF, R_F = 1M Ω, Xtal = ABM10W-25.0000MHZ-7-B1U-T3. Optimum values will vary depending on board layout.

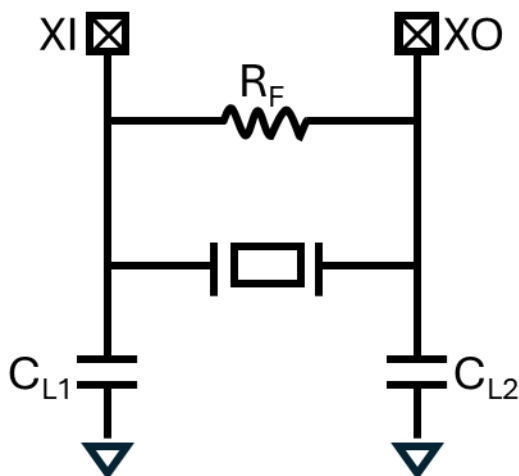
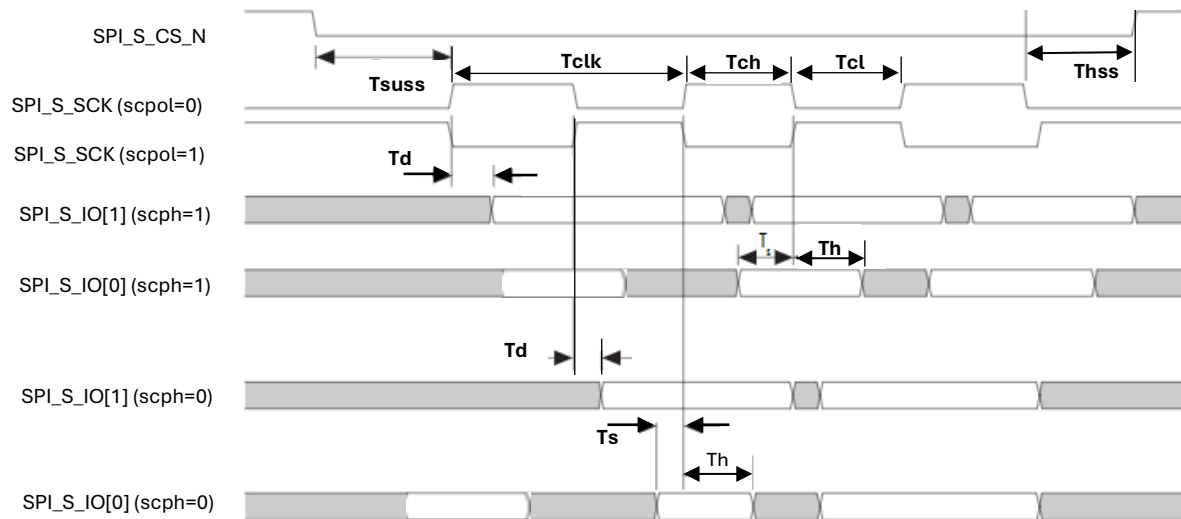


Figure 16: Recommended Xtal Configuration

9 TIMING SPECIFICATIONS

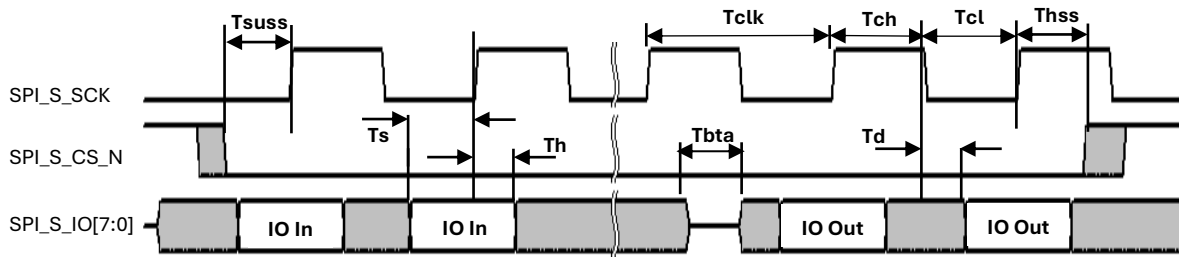
9.1 SPI SLAVE INTERFACE

9.1.1 SPI Slave Single Lane Mode



Symbol	Description	Min	Max	Unit	Notes
T_{clk}	SCK Clock Period	15	—	ns	1
T_{ch}	SCK Clock High Time	7.5	—	ns	
T_{cl}	CLK Clock Low Time	7.5	—	ns	
T_s	SPI_S_IO0 (MOSI) Setup time	2	—	ns	
T_h	SPI_S_IO0 (MOSI) Hold time	1	—	ns	
T_d	SPI_S_IO1 (MISO) Output Delay	1.5	5.5	ns	
T_{suss}	Setup time SPI_SS valid before first clock edge	5	—	ns	
T_{hss}	Hold time SPI_SS valid after last clock edge	3	—	ns	
C_{OUT}	Maximum capacitive load	-	10	pf	

9.1.2 SPI Slave Dual/Quad/Octal Mode



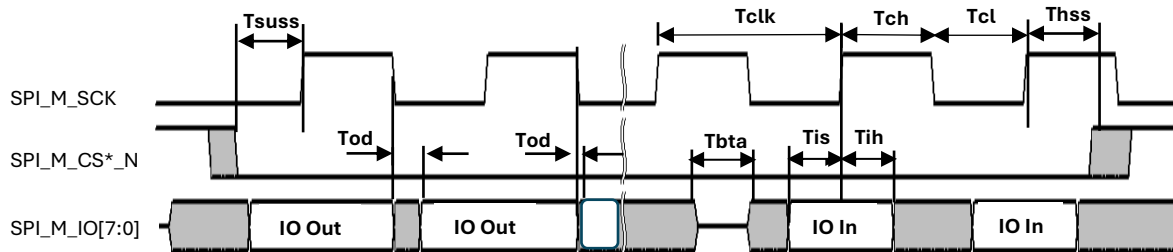
Symbol	Description	Min	Max	Unit	Notes
T_{clk}	SCK Clock Period	15	—	ns	1
T_{ch}	SCK Clock High Time	7.5	—	ns	
T_{cl}	CLK Clock Low Time	7.5	—	ns	
T_s	SPI_S_IO[7:0] Input Setup time	2	—	ns	
T_h	SPI_S_IO[7:0] input Hold time	1	—	ns	
T_d	SPI_S_IO[7:0] Output Delay	1.5	5.5	ns	
T_{suss}	Setup time SPI_SS valid before first clock edge	5	—	ns	
T_{hss}	Hold time SPI_SS valid after last clock edge	3	—	ns	
T_{bta}	Bus Turnaround time	-	3.5	ns	
C_{OUT}	Maximum capacitive load	-	10	pf	

Notes:

1. The SCK frequency is also limited by internal clock settings. Please refer to section 3.7.1.

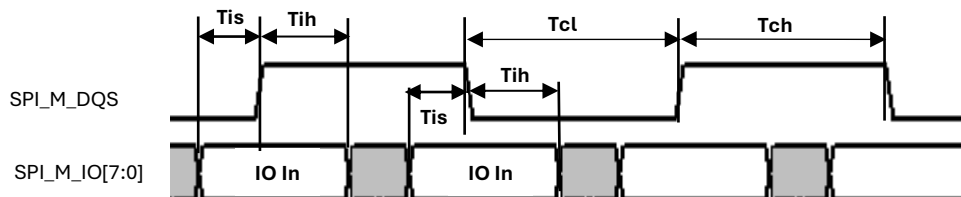
9.2 SPI MASTER INTERFACE

9.2.1 SPI Master Single Data Rate Mode



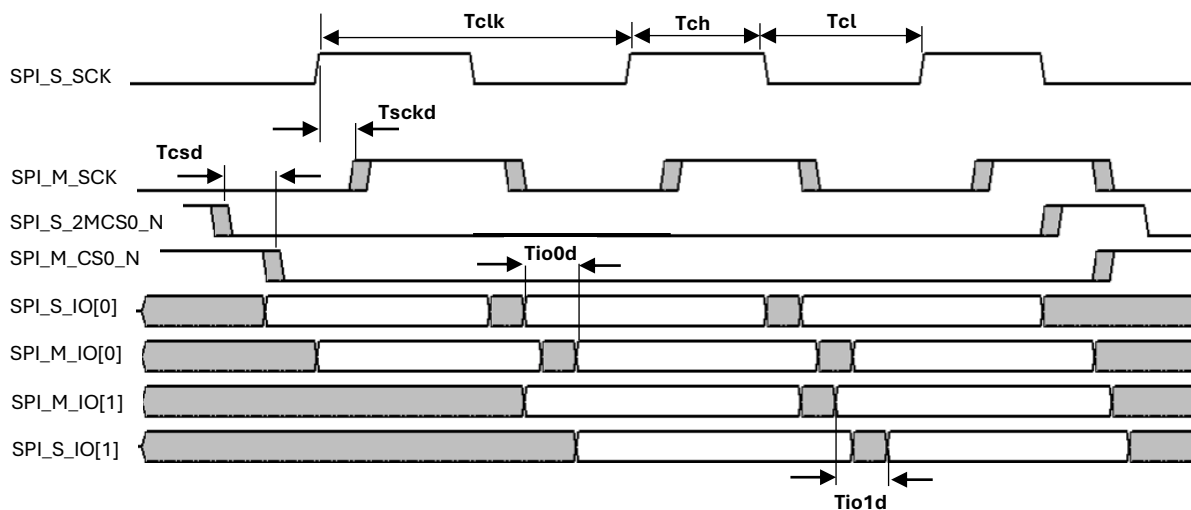
Symbol	Description	Min	Max	Unit	Notes
T_{clk}	SCK Clock Period	10	—	ns	
T_{ch}	SCK Clock High Time	5	—	ns	
T_{cl}	CLK Clock Low Time	5	—	ns	
T_{od}	SPI_M_IO[7:0] Output Delay	0	1.8	ns	
T_{is}	SPI_M_IO[7:0] input Setup time	1.25	—	ns	
T_{ih}	SPI_M_IO[7:0] Input Hold Time	0	-	ns	
T_{suss}	Setup time SPI_SS valid before first clock edge	1.8	—	ns	
T_{hss}	Hold time SPI_SS valid after last clock edge	5	—	ns	
T_{bta}	Bus Turnaround time	-	3.5	ns	
C_{OUT}	Maximum capacitive load	-	10	pf	

9.2.2 SPI Master DQS Dual Data Rate



Symbol	Description	Min	Max	Unit	Notes
T_{clk}	SCK Clock Period	10	—	ns	
T_{ch}	SCK Clock High Time	5	—	ns	
T_{cl}	CLK Clock Low Time	5	—	ns	
T_{is}	SPI_M_IO[7:0] input Setup time	0.5	—	ns	
T_{ih}	SPI_M_IO[7:0] Input Hold Time	1.7	-	ns	

9.3 SPI DIRECT ACCESS (SPI SLAVE TO SPI MASTER FEEDTHROUGH)



Symbol	Description	Min	Max	Unit	Notes
T_{clk}	SCK Clock Period	N/A	—	ns	1
T_{ch}	SCK Clock High Time	N/A	—	ns	
T_{cl}	CLK Clock Low Time	N/A	—	ns	
T_{sckd}	SPI_S_SCK to SPI_M_SCK Delay	1.5	4	ns	
T_{csd}	SPI_S_2MCS0_N to SPI_M_CS0_N Delay	3.5	6.5	ns	

T_{io0d}	SPI_S_IO[0] to SPI_M_IO[0] Delay	3.5	6.5	ns	
T_{io1d}	SPI_M_IO[1] to SPI_S_IO[1] Delay	2.5	4.5	ns	
C_{OUT}	Maximum capacitive load	-	10	pf	

Notes:

1. The AKD1500 is only adding delays to the SPI signals. The minimum clock period depends on the Host's SPI Master and the Device's SPI Slave specifications.

10 POWER SEQUENCE RECOMMENDATIONS

10.1 POWER ON SEQUENCE

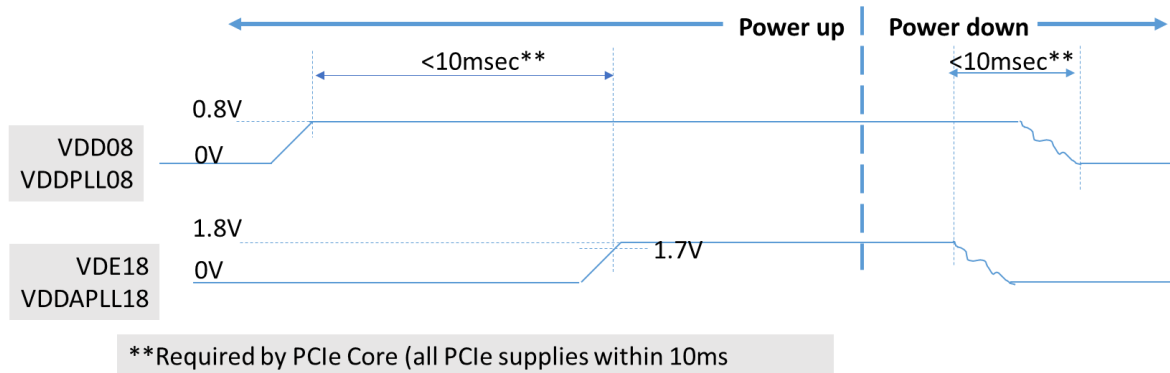


Figure 17: Power Sequence Diagram

10.1.1 General

Turn on from internal power supply to external power supply. (i.e. 0.8V core voltage first, VDE18 last.)

10.2 POWER OFF SEQUENCE

10.2.1 General

Turn off from external power supply to internal power supply (i.e. VDE18 shuts off first, 0.8 shuts off last).

11 LAYOUT CONSIDERATIONS

11.1 GROUND

We recommend a solid common ground plane for all analog and digital signals.

11.2 RECOMMENDED TEST POINTS

- PWR_GOOD. This will allow verification that the AKD1500 is out of reset.
- The 0.8V, 1.8V, and 3.3V (if applicable) power supplies. This will allow verification that the device is getting correct and clean power.
- All SPI_S and SPI_M signals that are used in your design. This will help to pinpoint HW/SW issues and facilitate faster bring up.
- SPI_S_SCKX. This pin will output the system clock divided by 16 when OP_MODE1 is pulled high. This is a sign of life indicator that is useful for design bring up.
- OSC_XI pin. Recommended if the device clock source is external. If the xtal is used, the xtal trim caps can be used as test points to verify the xtal is running.

11.3 DECOUPLING

We recommend one 01005 bypass cap on each power ball under the AKD1500. The 01005 body size allows the caps to be located directly between the vias for the power and ground balls of the device. This will minimize inductance and maximize the effectiveness of the bypass caps. There are a total of 43 such caps. If this is a cost issue for your design and you choose to modify this recommendation, you should run a power analysis simulation of your PCB design to guarantee power integrity. We recommend always adding the footprints for fully bypassing every power pin as described above, even if you don't intend to install the parts. This will make debug possible if it becomes necessary.

Analog supplies (VDDPLL08, VDDAPLL18, VP08, VPH33, VPTX008, VPTX108) should be filtered using a circuit similar to the one shown in Figure 18: Filtering analog supply lines.

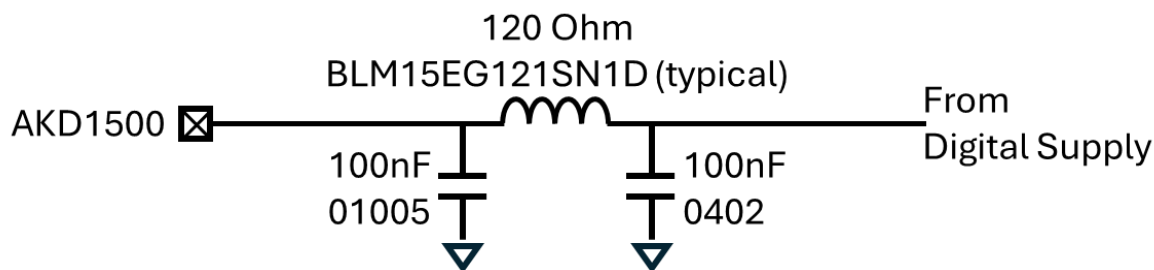


Figure 18: Filtering analog supply lines

A conservative implementation for bulk decoupling uses a set of 10uF 0603, 22uF 0603, 100uF 1202 caps on the 1.8V supply, and two sets on the 0.8V supply. The bulk decoupling caps should be within an inch of the AKD1500.

11.4 PCIe

- Differential traces to edge connector should be 5 to 7 mils with a typical spacing of one to two times the trace width.
- Target transmission line impedance between 68 and 105 ohms (85 ohms will match the PCIe edge connector).
- Coupling caps on the p and n legs of the TX lanes should be 100nF and 0201 form factor. The coupling caps should be side-by-side in line with the differential lane routes. See Figure 19: PCIe lane routing.
- Maintain a continuous reference plane under PCIe differential pairs.
- We recommend that the TX lane coupling caps have an anti-pad in their reference plane. See Figure 19: PCIe lane routing.
- Skew between traces in differential pairs should be 5mils or less.
- Skew between lanes should be less than 5000 mils.
- Vias in the differential pairs should be minimized and balanced. 2 vias per leg max.
- Avoid 90° angles on traces.
- Remove inner planes and routes on PCIe edge connector.

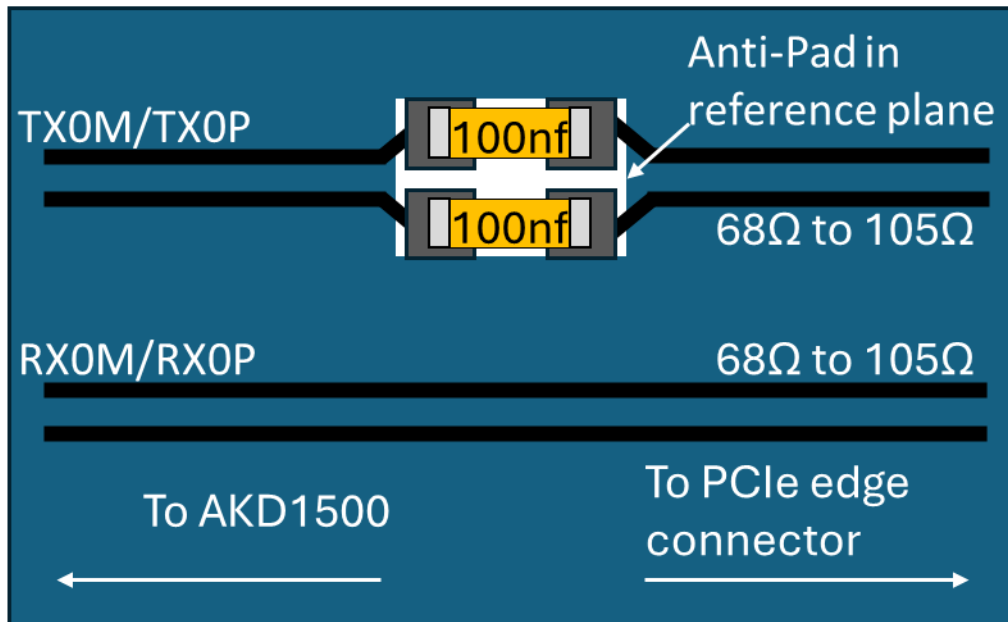


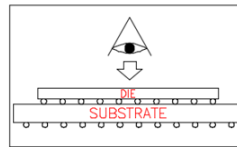
Figure 19: PCIe lane routing

11.5 SPI_S AND SPI_M

- Avoid trace stubs on SPI clocks.
- Use source termination at the source for longer SPI clock lines.
- Daisy chain or use the auxiliary SPI clock (SPI_M_SCKX) when connecting multiple SPI loads
- Maintain a continuous reference plane under the SPI clocks

12 BALL ASSIGNMENTS

12.1 BALL MAP



<PACKAGE Top View>

	1	2	3	4	5	6	7	8	9	10	11	12	13	
A	GND	VPH 33	VP08	VPTX1 08	GND	REFPA DCLK_P	TX0P	RX0P	RX1P	TX1P	GND	SPI_S_SCK	GND	A
B	GND	RESRE F	GND	VPTX0 08	GND	REFPA DCLK_M	TX0M	RX0M	RX1M	TX1M	GND	SPI_S_MODE0	SPI_S_MODE1	B
C	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	SPI_S_I00	GND	SPI_S_I01	C
D	VDD08	VDD08	VDD08	VDD08	VDD08	VDD08	VDD08	VDD08	VDE18	GND	SPI_S_I02	SPI_S_I03	SPI_S_I04	D
E	GND	GND	GND	GND	GND	GND	GND	GND	VDE18	GND	SPI_S_I05	GND	SPI_S_I06	E
F	VDD08	VDD08	VDD08	VDD08	VDD08	VDD08	VDD08	VDD08	VDE18	GND	SPI_S_I07	SPI_S_2MCS0_N	SPI_S_CS_N	F
G	GND	GND	GND	GND	GND	GND	GND	GND	VDE18	VDDAP LL18	GND	SPI_S_2MCS1_N	GND	G
H	VDD08	VDD08	VDD08	VDD08	VDD08	VDD08	VDD08	VDD08	VDE18	VDDPL L08	AVS_PL L	GND	OSC_XI	H
J	GND	GND	GND	GND	GND	GND	GND	VDE18	VDE18	VDE18	GND	GND	OSC_XO	J
K	VPD	TESTM ODE	VDE18	VDE18	VDE18	VDE18	VDE18	VQPS_eFUSE	VDDIO_eFUSE	GND	SPI_M_SCKX	SPI_M_CS1_N	GND	K
L	TAP_SE L	PWR_G OOD	GND	GND	GND	GND	GND	GND	GND	SPI_M_I07	SPI_M_I06	SPI_M_I01	SPI_M_I00	L
M	GND	SLEEP	OP_MO DE0	GPIO_0 3	GPIO_0 1	FUSE_CK	FUSE_EN	GND	SPI_M_CS0_N	SPI_M_I04	SPI_M_I02	GND	SPI_M_SCK	M
N	GND	PCIE_P ERST_N	OP_MO DE1	PCIE_H OST_S EL	GPIO_0 2	GPIO_0 0	SEL_CL K	SPI_M_RST_N	SPI_M_I05	GND	SPI_M_I03	SPI_M_DQS	GND	N
	1	2	3	4	5	6	7	8	9	10	11	12	13	

Figure 20: Ball Map

12.2 BALL DESCRIPTION

Interface	Pin	Symbol	Description
Configuration	M3	OP_MODE0	Source of internal clock: '0'=Xtal. '1'=Reserved
Configuration	N3	OP_MODE1	'1'=SAFE Mode (PLL setup bypassed); '0'=Normal mode.

Interface	Pin	Symbol	Description
Configuration	N4	PCIE_HOST_SEL	'1' = PCIe is Host; '0' = SPI Slave is host (this pin is ignored if OP_MODE1 is '1'. Both hosts will be active)
Configuration	L2	PWR_GOOD	Power Good – AKD1500 master reset
Configuration	N7	SEL_CLK	'1'=select digital CLK input for OSC_XI_CLK pad; '0'=select OSC (XI/XO)
Configuration	M2	SLEEP	0'=normal mode; '1'=low power
GPIO	N6	GPIO_00	General purpose IO
GPIO	M5	GPIO_01	General purpose IO/PLL lock
GPIO	N5	GPIO_02	General purpose IO/IRQ High priority
GPIO	M4	GPIO_03	General purpose IO/IRQ
OSC	H13	OSC_XI	Xtal Oscillator feedback/Ext clock input
OSC	J13	OSC_XO	Xtal Oscillator output
PCIe	N2	PCIE_PERST_N	PCIe slot reset
PCIe	B6	REFPADCLK_M	PCIe -ref clock
PCIe	A6	REFPADCLK_P	PCIe +ref clock
PCIe	B2	RESREF	PCIe Calibration Resistor
PCIe	B8	RX0M	PCIe -Rx Lane 0
PCIe	A8	RX0P	PCIe +Rx Lane 0
PCIe	B9	RX1M	PCIe -Rx Lane 1
PCIe	A9	RX1P	PCIe +Rx Lane 1
PCIe	B7	TX0M	PCIe -Tx Lane 0
PCIe	A7	TX0P	PCIe +Tx Lane 0
PCIe	B10	TX1M	PCIe -Tx Lane 1
PCIe	A10	TX1P	PCIe +Tx Lane 1
PCIe	A3	VP08	Low Voltage Supply. This signal can be supplied from the same off-chip source as the chip 0.8V VDD core supply, but must be isolated on the board through a ferrite bead and must not be connected to any other core supply in the package or on the die
PCIe	A2	VPH33	High Voltage Supply. High voltage supply of the PHY. This signal is 3.3V. This power supply should be isolated on the board through a ferrite bead and must not be shared with any other supplies in the package or on the die.

Interface	Pin	Symbol	Description
PCle	B4	VPTX008	Transmitter Supply Voltage. Similar to VP08, this supply can come from the same off-chip source as the chip 0.8V VDD supply, but must be isolated on the board through a ferrite bead and must not be connected to any other core supply in the package or on the die. Sharing VPTXx08 and VP08 connections adds RX asynchronous noise on the transmitter power supply. Keep them isolated until out on the PCB board
PCle	A4	VPTX108	Transmitter Supply Voltage. Similar to VP08, this supply can come from the same off-chip source as the chip 0.8V VDD supply, but must be isolated on the board through a ferrite bead and must not be connected to any other core supply in the package or on the die. Sharing VPTXx08 and VP08 connections adds RX asynchronous noise on the transmitter power supply. Keep them isolated until out on the PCB board
SPI Master	M9	SPI_M_CS0_N	SPI Master Chip Sel 0
SPI Master	K12	SPI_M_CS1_N	SPI Master Chip Sel 1
SPI Master	N12	SPI_M_DQS	SPI data strobe in some modes
SPI Master	L13	SPI_M_IO0	SPI Master Data
SPI Master	L12	SPI_M_IO1	SPI Master Data
SPI Master	M11	SPI_M_IO2	SPI Master Data
SPI Master	N11	SPI_M_IO3	SPI Master Data
SPI Master	M10	SPI_M_IO4	SPI Master Data
SPI Master	N9	SPI_M_IO5	SPI Master Data
SPI Master	L11	SPI_M_IO6	SPI Master Data
SPI Master	L10	SPI_M_IO7	SPI Master Data
SPI Master	N8	SPI_M_RST_N	SPI Master reset
SPI Master	M13	SPI_M_SCK	SPI Master Clock (primary)
SPI Master	K11	SPI_M_SCKX	SPI Master Clock (secondary)

Interface	Pin	Symbol	Description
SPI Slave	F12	SPI_S_2MCS0_N	SPI Master I/F Chip Sel 0
SPI Slave	G12	SPI_S_2MCS1_N	SPI Master I/F Chip Sel 1
SPI Slave	F13	SPI_S_CS_N	SPI Slave Chip Sel
SPI Slave	C11	SPI_S_IO0	SPI Slave Data
SPI Slave	C13	SPI_S_IO1	SPI Slave Data
SPI Slave	D11	SPI_S_IO2	SPI Slave Data
SPI Slave	D12	SPI_S_IO3	SPI Slave Data
SPI Slave	D13	SPI_S_IO4	SPI Slave Data
SPI Slave	E11	SPI_S_IO5	SPI Slave Data
SPI Slave	E13	SPI_S_IO6	SPI Slave Data
SPI Slave	F11	SPI_S_IO7	SPI Slave Data
SPI Slave	B12	SPI_S_MODE0	SPI Frame format input signal. Indicates the mode in which the SPI transfer is happening. '00'=Standard SPI mode; '01'=SPI Dual Mode; '10'=SPI Quad mode; '11'=SPI Octal mode
SPI Slave	B13	SPI_S_MODE1	
SPI Slave	A12	SPI_S_SCK	
Test	M6	FUSE_CHK	Do not connect
Test	M7	FUSE_EN	Do not connect
Test	L1	TAP_SEL	'0'=normal operation
Test	K2	TESTMODE	'0'=normal operation
Test	K9	VDDIO_eFUSE	Do not connect
Test	K1	VPD	Do not connect
Test	K8	VQPS_eFUSE	Do not connect
Power	H11	AVS_PLL	VSS for PLL
Power	A1	GND	
Power	A11	GND	
Power	A13	GND	
Power	A5	GND	
Power	B1	GND	
Power	B11	GND	
Power	B3	GND	
Power	B5	GND	
Power	C1	GND	
Power	C10	GND	
Power	C12	GND	
Power	C2	GND	
Power	C3	GND	

Interface	Pin	Symbol	Description
Power	C4	GND	
Power	C5	GND	
Power	C6	GND	
Power	C7	GND	
Power	C8	GND	
Power	C9	GND	
Power	D10	GND	
Power	E1	GND	
Power	E10	GND	
Power	E12	GND	
Power	E2	GND	
Power	E3	GND	
Power	E4	GND	
Power	E5	GND	
Power	E6	GND	
Power	E7	GND	
Power	E8	GND	
Power	F10	GND	
Power	G1	GND	
Power	G11	GND	
Power	G13	GND	
Power	G2	GND	
Power	G3	GND	
Power	G4	GND	
Power	G5	GND	
Power	G6	GND	
Power	G7	GND	
Power	G8	GND	
Power	H12	GND	
Power	J1	GND	
Power	J11	GND	
Power	J12	GND	
Power	J2	GND	
Power	J3	GND	
Power	J4	GND	
Power	J5	GND	

Interface	Pin	Symbol	Description
Power	J6	GND	
Power	J7	GND	
Power	K10	GND	
Power	K13	GND	
Power	L3	GND	
Power	L4	GND	
Power	L5	GND	
Power	L6	GND	
Power	L7	GND	
Power	L8	GND	
Power	L9	GND	
Power	M1	GND	
Power	M12	GND	
Power	M8	GND	
Power	N1	GND	
Power	N10	GND	
Power	N13	GND	
Power	D1	VDD08	0.8V core voltage
Power	D2	VDD08	0.8V core voltage
Power	D3	VDD08	0.8V core voltage
Power	D4	VDD08	0.8V core voltage
Power	D5	VDD08	0.8V core voltage
Power	D6	VDD08	0.8V core voltage
Power	D7	VDD08	0.8V core voltage
Power	D8	VDD08	0.8V core voltage
Power	F1	VDD08	0.8V core voltage
Power	F2	VDD08	0.8V core voltage
Power	F3	VDD08	0.8V core voltage
Power	F4	VDD08	0.8V core voltage
Power	F5	VDD08	0.8V core voltage
Power	F6	VDD08	0.8V core voltage
Power	F7	VDD08	0.8V core voltage
Power	F8	VDD08	0.8V core voltage
Power	H1	VDD08	0.8V core voltage
Power	H2	VDD08	0.8V core voltage
Power	H3	VDD08	0.8V core voltage

Interface	Pin	Symbol	Description
Power	H4	VDD08	0.8V core voltage
Power	H5	VDD08	0.8V core voltage
Power	H6	VDD08	0.8V core voltage
Power	H7	VDD08	0.8V core voltage
Power	H8	VDD08	0.8V core voltage
Power	G10	VDDAPLL18	1.8V PLL voltage - isolate with ferrite bead
Power	H10	VDDPLL08	0.8V PLL core voltage - isolate with ferrite bead
Power	D9	VDE18	1.8V i/o voltage
Power	E9	VDE18	1.8V i/o voltage
Power	F9	VDE18	1.8V i/o voltage
Power	G9	VDE18	1.8V i/o voltage
Power	H9	VDE18	1.8V i/o voltage
Power	J10	VDE18	1.8V i/o voltage
Power	J8	VDE18	1.8V i/o voltage
Power	J9	VDE18	1.8V i/o voltage
Power	K3	VDE18	1.8V i/o voltage
Power	K4	VDE18	1.8V i/o voltage
Power	K5	VDE18	1.8V i/o voltage
Power	K6	VDE18	1.8V i/o voltage
Power	K7	VDE18	1.8V i/o voltage

Figure 21: Ball Descriptions

13 THERMAL

Symbol	Value	Units	Description
θ_{jb}	14.59	°C/W	Thermal resistance junction to board
θ_{ja}	28.79	°C/W	Thermal resistance junction to ambient

Conditions: $T_a=85(^{\circ}\text{C})$, Power=1.2(W)

Figure 22: Thermal Characteristics

14 MECHANICAL DIMENSIONS FOR MFCLFBGA169 7x7MM

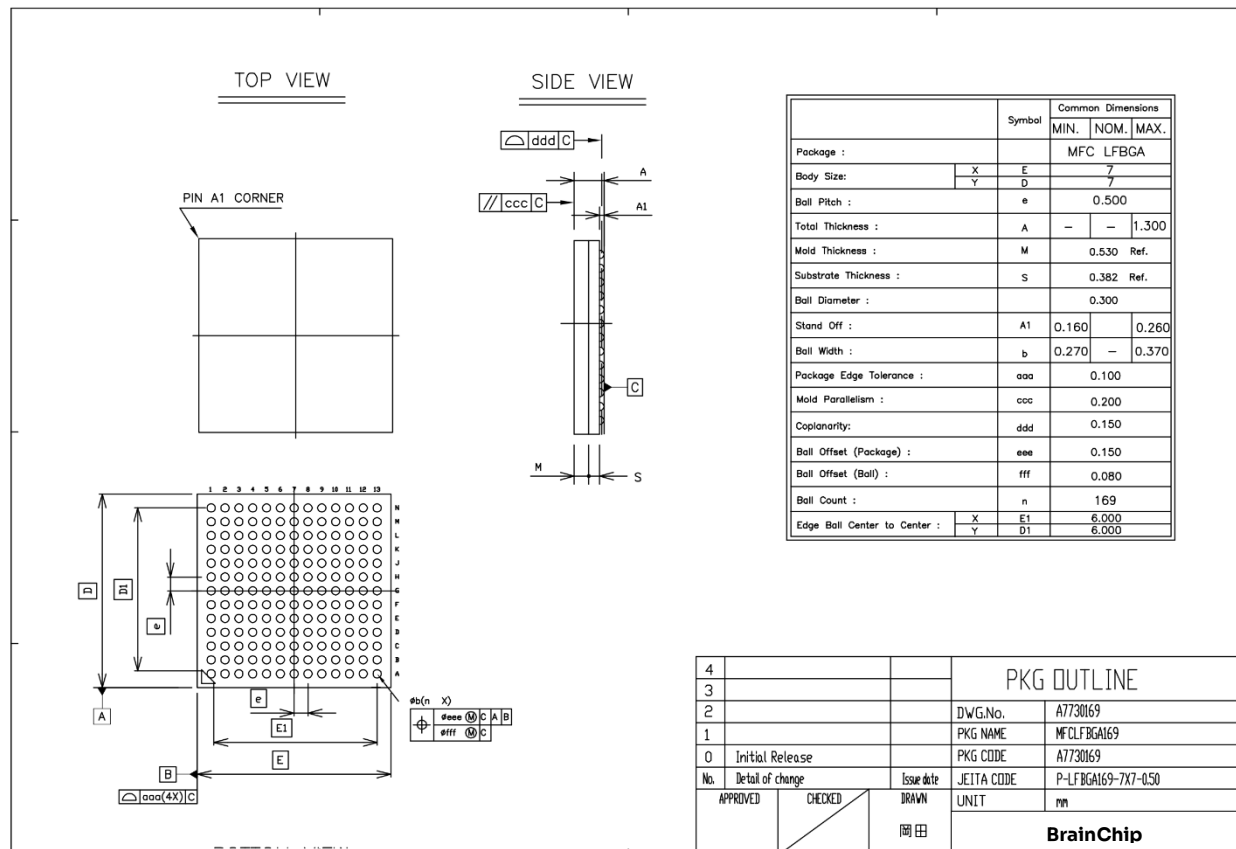


Figure 23: Mechanical Package Dimensions (MFCLFBGA169)

15 SHELF-LIFE AND BALL COMPOSITION

15.1 MOISTURE SENSITIVITY LEVEL

The MSL is 3. The shelf-life in a Moisture Barrier Bag is 12-months. After this time, it is recommended to bake the chips for 24 hrs. at $(125 \pm 5)^\circ\text{C}$ in heat-resistant containers.

15.2 BALL COMPOSITION

Ball Composition is Sn-1.2Ag-0.5Cu-0.05Ni

16 APPLICATION EXAMPLES

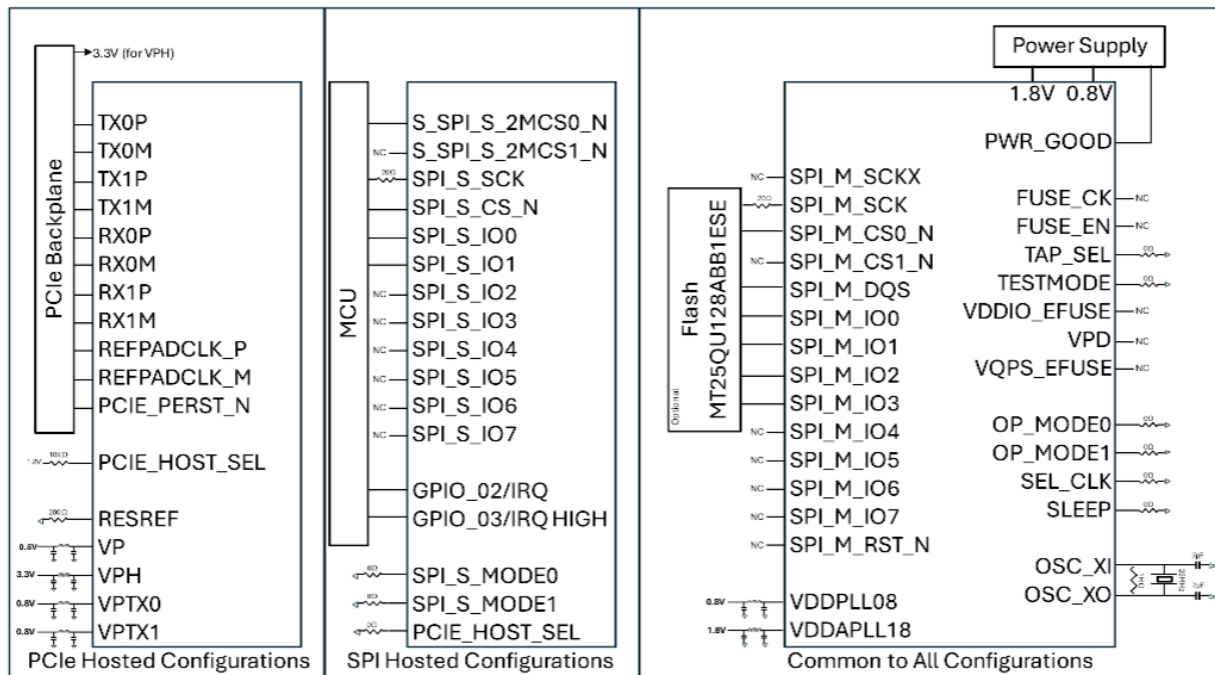


Figure 24: Application Examples

17 ORDERING INFORMATION

This section defines the AKD1500 part number taxonomy and currently available orderable SKUs. The part number structure follows a fixed-length positional format. All fields are always present in the Orderable Part Number.

17.1 DEVICE NOMENCLATURE

BrainChip Akida — Device Nomenclature

	1	2	3	4	5	6	7	8	9	10
Generic PN:	—	AKD	1500	P	F	I	04	0	—	—
Orderable PN:	—	AKD	1500	P	F	I	04	0	R	A
	PREFIX	BRAND	SERIES	INTERFACE	PACKAGE	TEMP GRADE	CLOCK	FEAT / CONFIG	SHIPPING	SILICON REVISION

1. PREFIX

(blank) = Production-qualified device
ES = Engineering Sample (pre-production)
CS = Customer-Specific (custom order)
Requires Customer Agreement reference

2. BRAND

AKD = Akida neuromorphic family
TBD = GenAI / TENNs product line (future)

3. SERIES

1500 = AKD1500 — 32-core, PCIe / SPI host
2500 = AKD2500 — Pico-based, I2C host
TBD = Future variants

4. INTERFACE / CONNECTIVITY

P = PCIe x2 Gen2
S = SPI Slave
I = I2C
U = USB | M = MIPI CSI-2 | E = Ethernet (future)

5. PACKAGE

F = 7×7mm FCBGA169 (MFCLFBGA169)
D = Die / bare (future)
Q = QFN | W = WLCSP (future)

6. TEMP GRADE

C = Commercial 0°C to +70°C
I = Industrial -25°C to +85°C
M = Military -55°C to +125°C
E = Extended -40°C to +125°C

7. CLOCK

04 = 400 MHz (confirmed default)
02 = 200 MHz | 03 = 300 MHz (confirm w/ eng.)
05 = 500 MHz (future)

8. FEAT / CONFIG * (always present)

0 = Standard full-featured (always use)
1 = HRC disabled (Image front-end fused off)
2 = Edge Learning disabled (inference-only)
3 = HRC + Edge Learning disabled

9. SHIPPING **

R = Tape & Reel (volume production)
B = Bulk / Tube (prototyping / ES / CS)
** Orderable Part Number only

10. SILICON REVISION **

A = Rev A (first production silicon)
B = Rev B, C = Rev C (subsequent)
** Must match lot trace code # character

* Feature / Config: always present. 0 = full-featured. Fixed-length for automated parsing.

** Shipping and Silicon Revision in Orderable Part Number only — omit from Generic Part Number.

Italic green = anticipated future codes. Not yet active. Require formal taxonomy revision.

Generic PN: AKD1500PFIO40

Orderable PN: AKD1500PFIO40RA

ES example: ESAKD1500PFIO40BA

CS example: CSAKD2500IFIO30BA

Figure 25: AKD1500 Device Nomenclature. * Shipping code in Orderable PN only. † Silicon Revision in Orderable PN only. Green dashed = Feature/Config field (always present; 0 = standard full-featured).

The Generic Part Number uses 7 fields (fields 2–8: Brand, Series, Interface, Package, Temp Grade, Clock, and FEAT/CONFIG). The Orderable Part Number (OPN) uses all 10 fields, adding Prefix (field 1, e.g., ES for Engineering Sample, CS for Custom Sample), Shipping (field 9), and Silicon Revision (field 10).

17.2 ORDERING GUIDE

The following table lists all orderable AKD1500 configurations in PCIe variants (up to 400 MHz) across Commercial, Industrial, Military, and Extended temperature grades. SPI variants (up to 400 MHz) part numbers are available in the AKD1500 SPI datasheet. Pricing is available upon request, contact BrainChip Sales at sales@brainchipinc.com for military parts and large orders. Part numbers follow BrainChip device nomenclature. Table will be updated as new configurations become available.

Orderable Part Number	Interface	Package	Temp Grade	Clock	Feature / Config	Shipping	Silicon Revision
AKD1500 PCIe — up to 400 MHz (Prototype, Pre-Production & Mass Production)							
ESAKD1500PFC040BA	PCIe x2	7×7mm FCBGA169	Commercial (0 to +70°C)	400 MHz	Standard	Bulk / Tube	Rev A
AKD1500PFC040RA	PCIe x2	7×7mm FCBGA169	Commercial (0 to +70°C)	400 MHz	Standard	Tape & Reel	Rev A
AKD1500PFC040BA	PCIe x2	7×7mm FCBGA169	Commercial (0 to +70°C)	400 MHz	Standard	Bulk / Tube	Rev A
ESAKD1500PFI040BA	PCIe x2	7×7mm FCBGA169	Industrial (-40 to +85°C)	400 MHz	Standard	Bulk / Tube	Rev A
AKD1500PFI040RA	PCIe x2	7×7mm FCBGA169	Industrial (-40 to +85°C)	400 MHz	Standard	Tape & Reel	Rev A
AKD1500PFI040BA	PCIe x2	7×7mm FCBGA169	Industrial (-40 to +85°C)	400 MHz	Standard	Bulk / Tube	Rev A
AKD1500PFE030RA	PCIe x2	7×7mm FCBGA169	Extended (-40 to +125°C)	300 MHz	Standard	Tape & Reel	Rev A
AKD1500PFE030BA	PCIe x2	7×7mm FCBGA169	Extended (-40 to +125°C)	300 MHz	Standard	Bulk / Tube	Rev A

Note: Part numbers follow BrainChip device nomenclature. For product availability, custom configurations (CS prefix), or OEM pricing, contact BrainChip sales. This table will be updated as new variants become available.